

**ROCHESTER INSTITUTE OF TECHNOLOGY
MICROELECTRONIC ENGINEERING**

Surface Analysis

Dr. Lynn Fuller

Dr. Fuller's Webpage: <http://people.rit.edu/lffeee>

Microelectronic Engineering

Rochester Institute of Technology

82 Lomb Memorial Drive

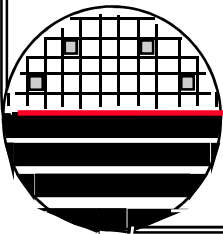
Rochester, NY 14623-5604

Tel (585) 475-2035

Fax (585) 475-5041

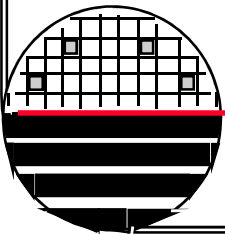
Email: Lynn.Fuller@rit.edu

MicroE webpage: <http://www.microe.rit.edu>



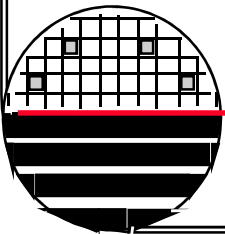
OUTLINE

Introduction
Scanning Electron Microscopy (SEM)
Transmission Electron Microscopy (TEM)
Atomic Force Microscopy (AFM)
Energy Dispersive Analysis of x-rays (EDAX)
Auger Electron Spectroscopy
X-ray Fluorescence Spectroscopy (XPS)
Secondary Ion Mass Spectroscopy (SIMS)
Capacitance Voltage Measurements
Surface Charge Analyzer



INTRODUCTION

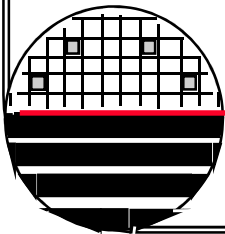
Surface analysis refers to a collection of techniques to get information about the chemical or physical nature of a surface. (few μm)



LEO EVO 50



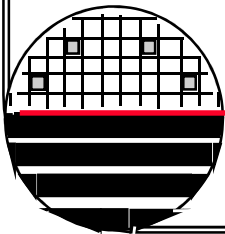
*Rochester Institute of Technology
Microelectronic Engineering*



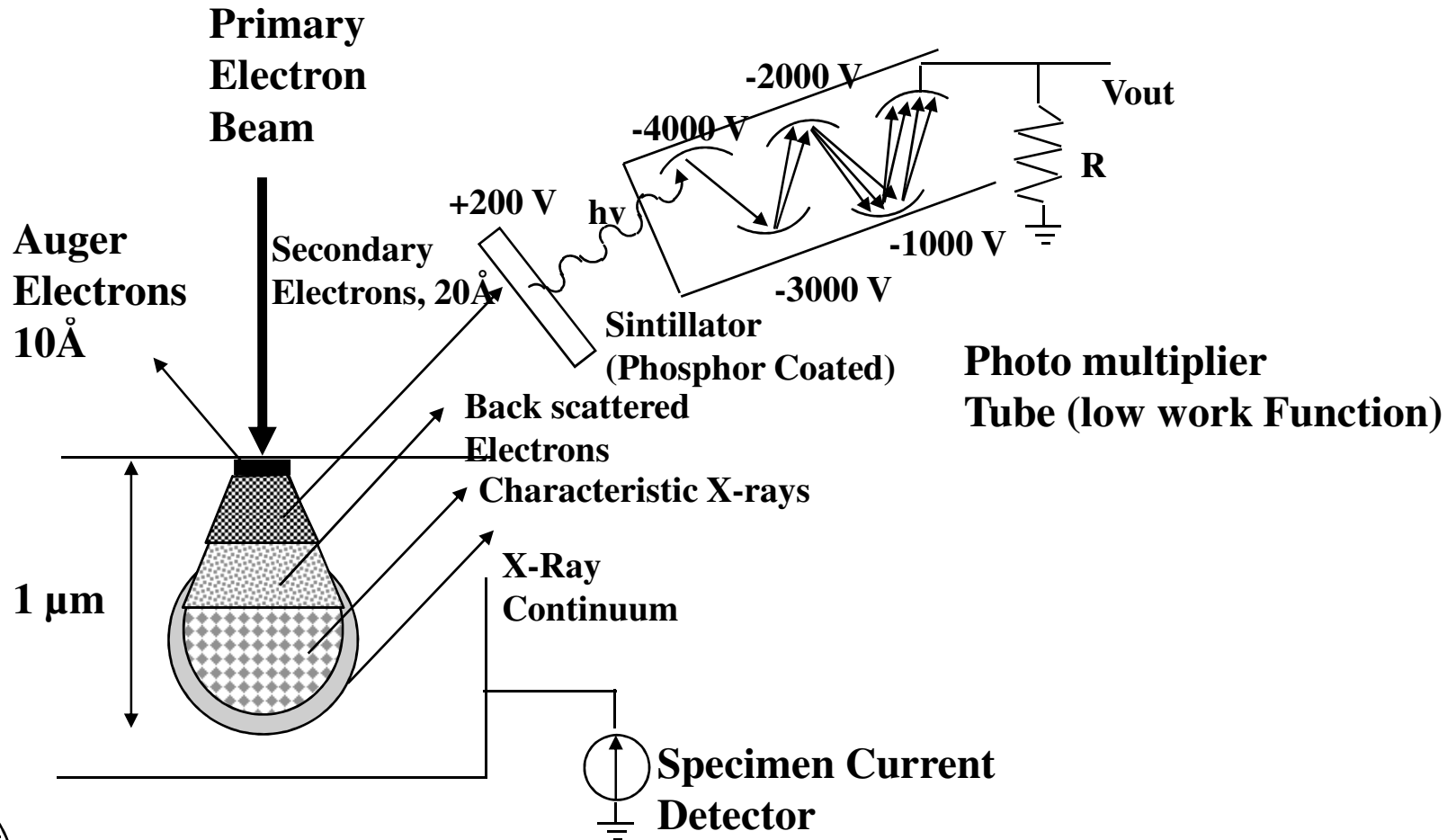
AMRAY 1830 1 & 2



*Rochester Institute of Technology
Microelectronic Engineering*

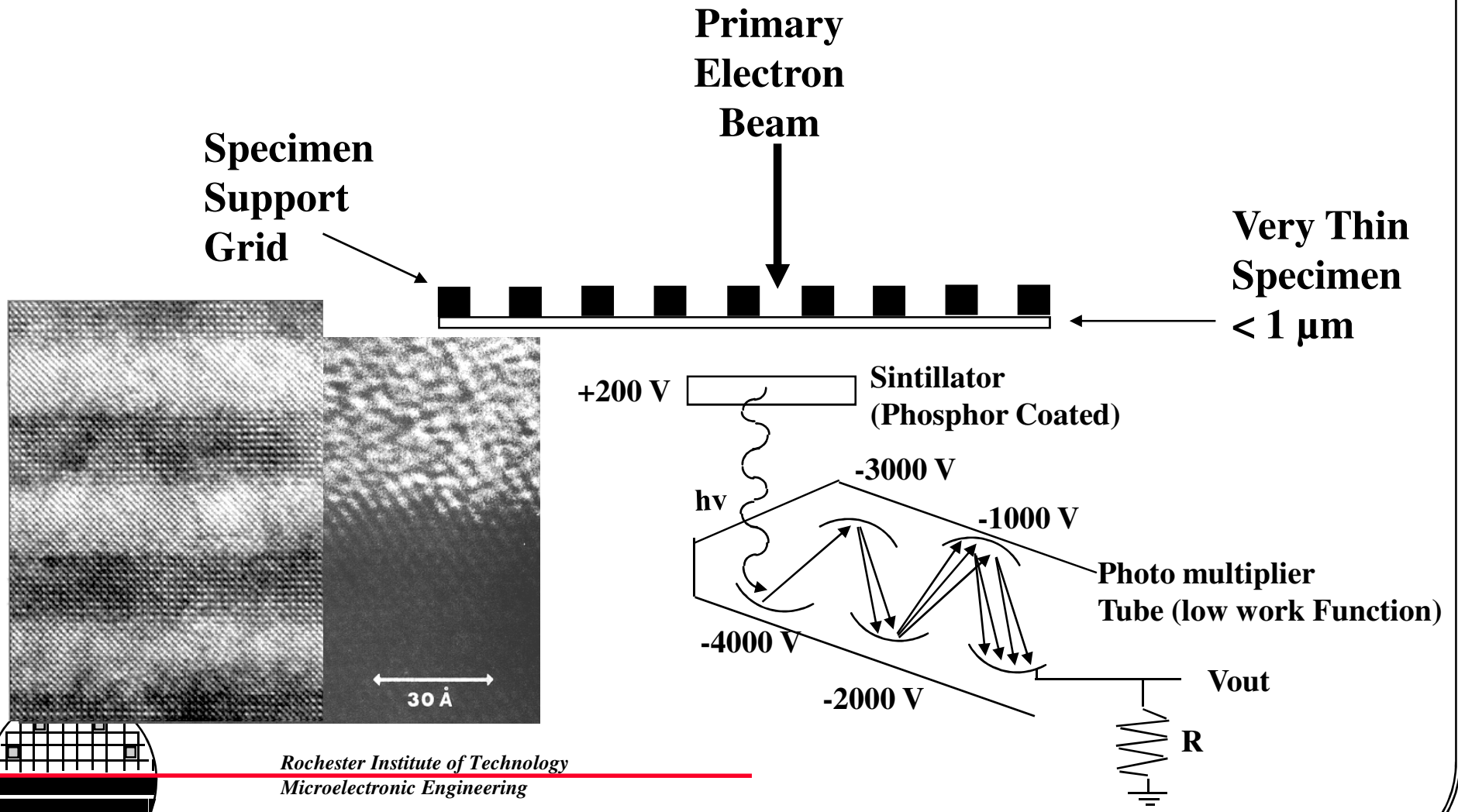


SCANNING ELECTRON MICROSCOPE (SEM)



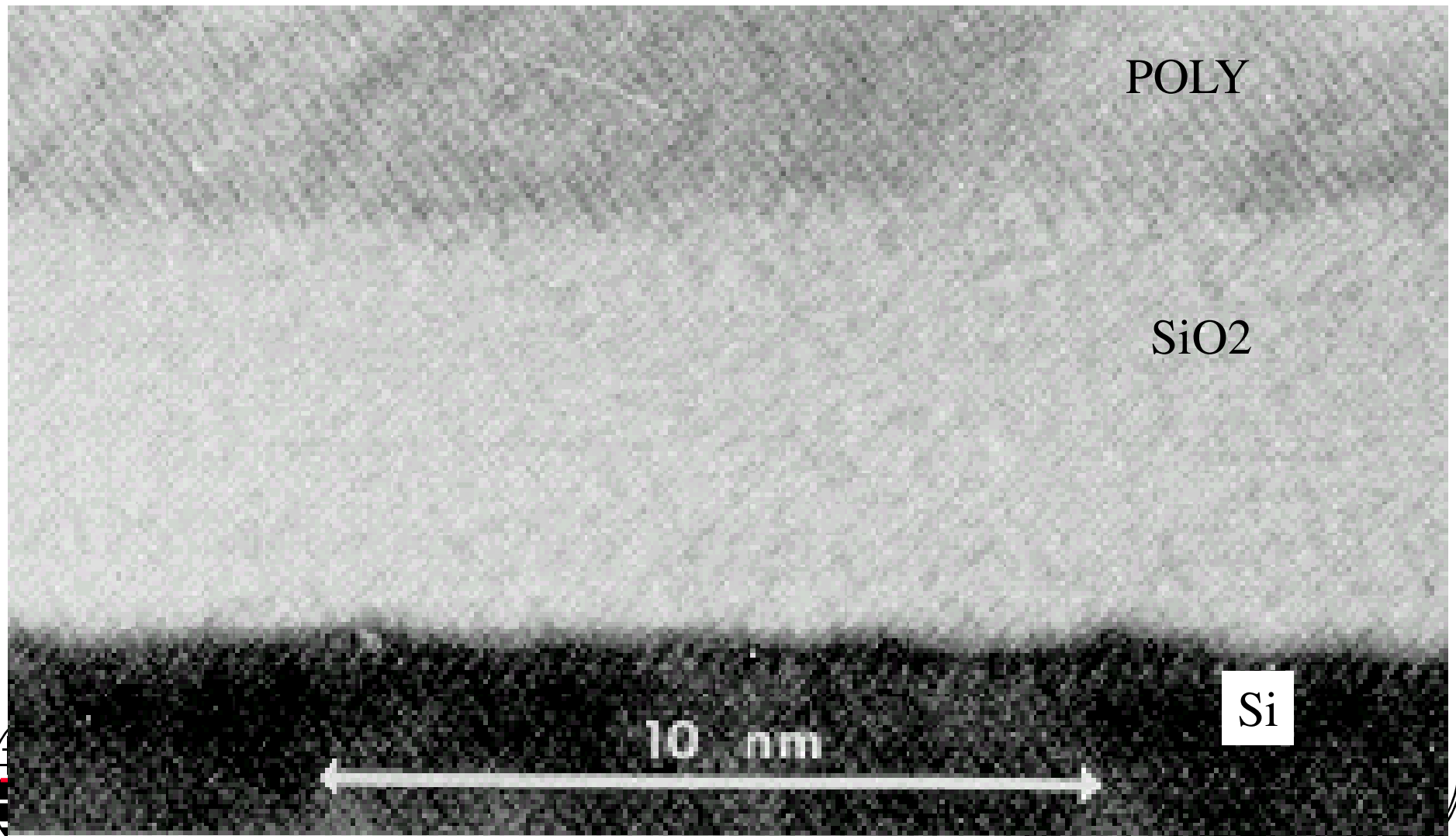
Rochester Institute of Technology
Microelectronic Engineering

TRANSMISSION ELECTRON MICROSCOPE

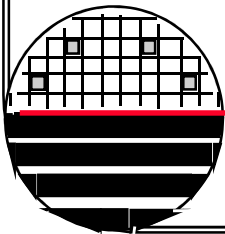


Rochester Institute of Technology
Microelectronic Engineering

TEM OF MOS STRUCTURE

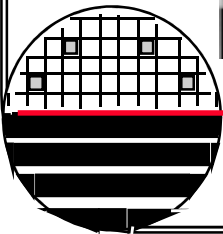
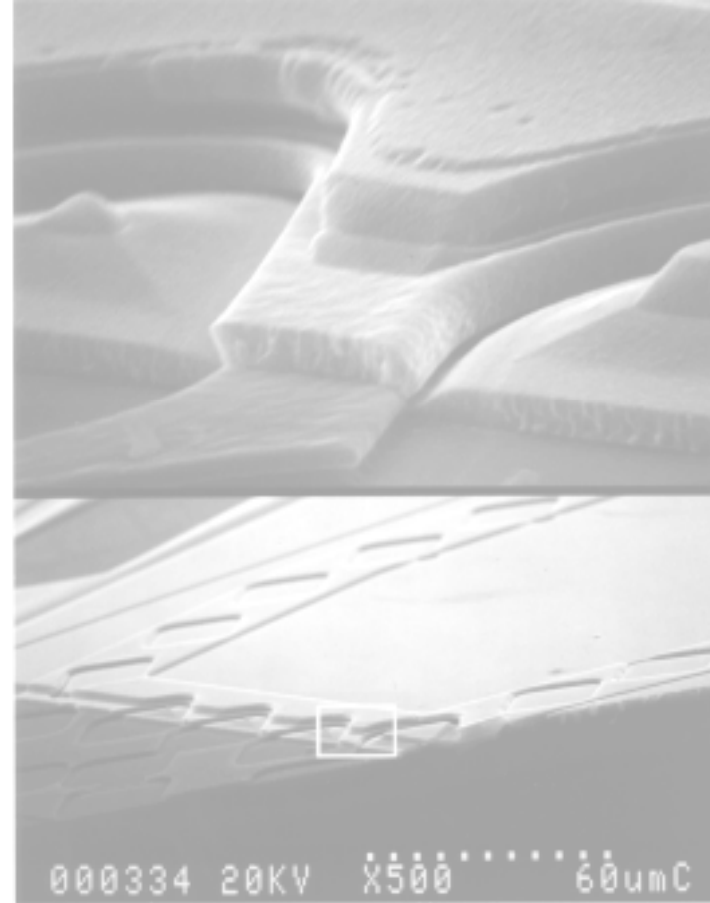
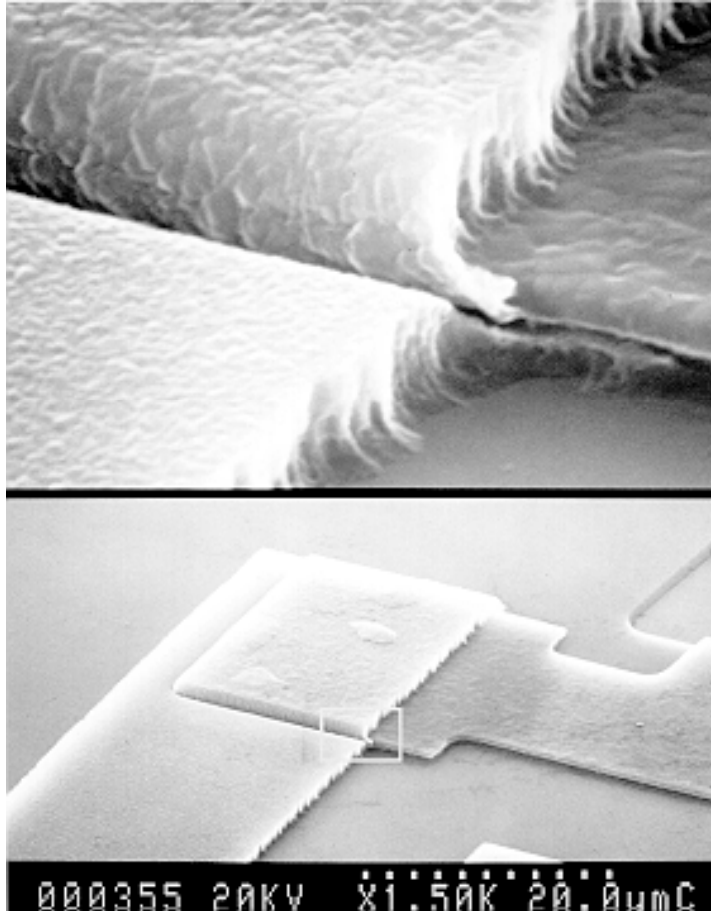


LEO EVO 50 SEM & EDAX



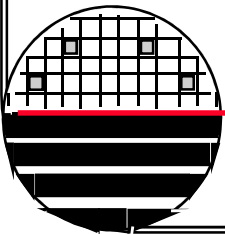
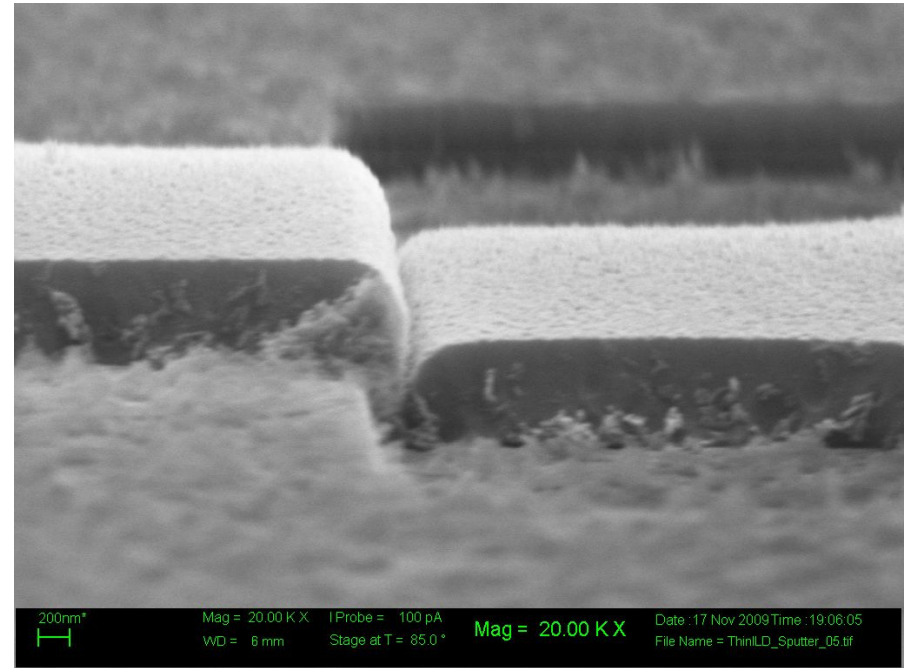
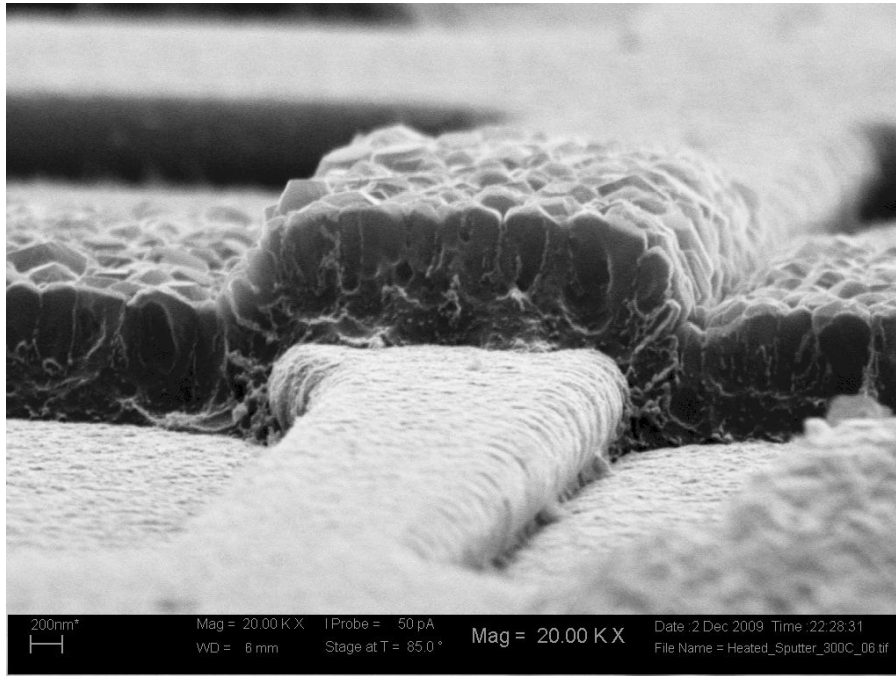
R
M

SEM EXAMPLES

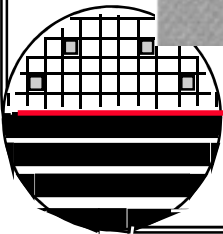
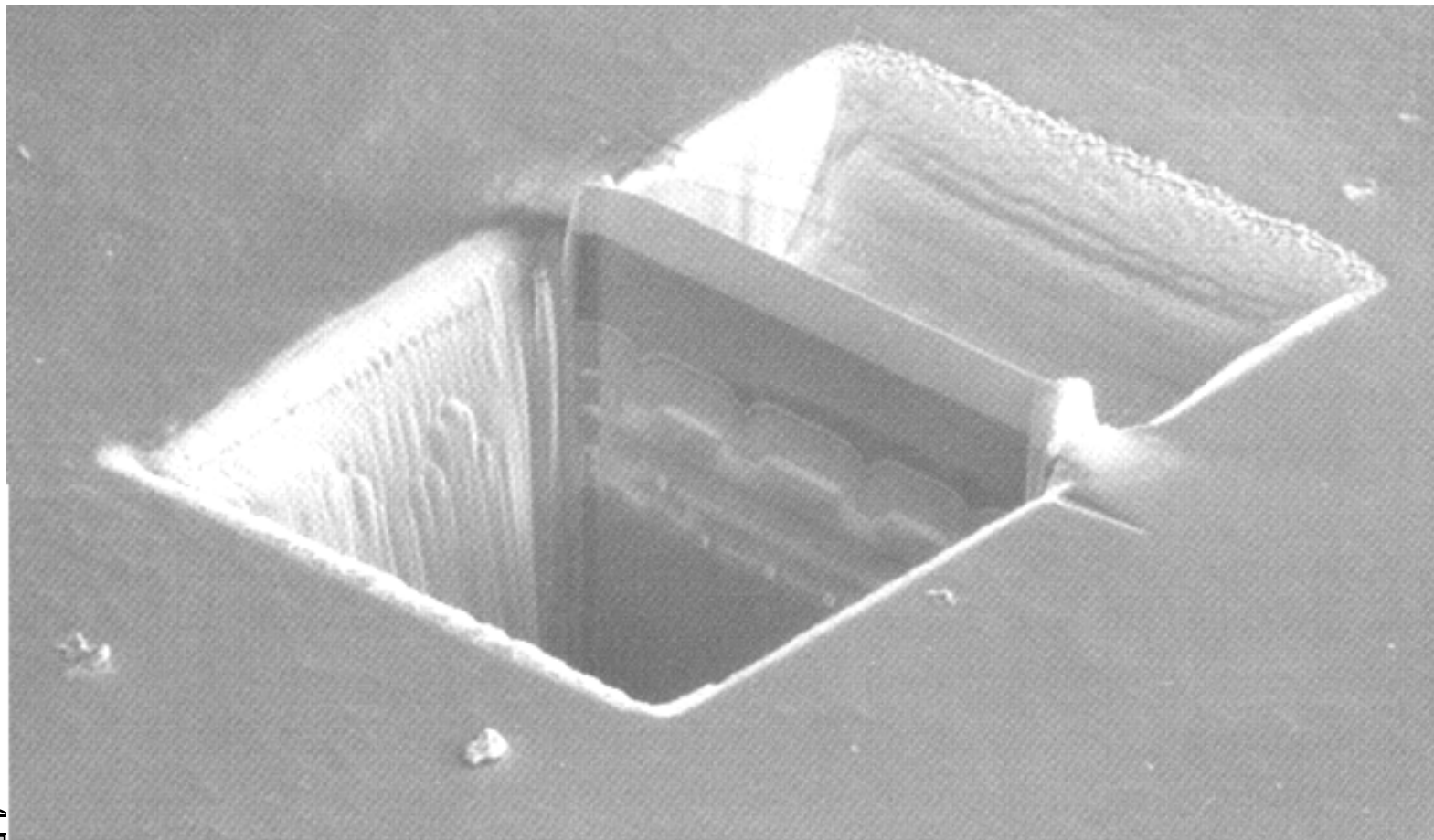


Rochester Institute of Technology
Microelectronic Engineering

SEM EXAMPLES

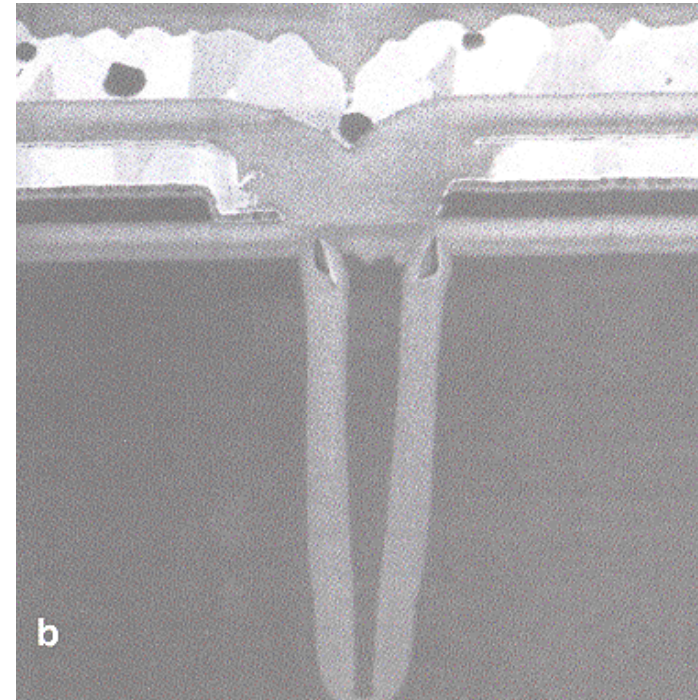
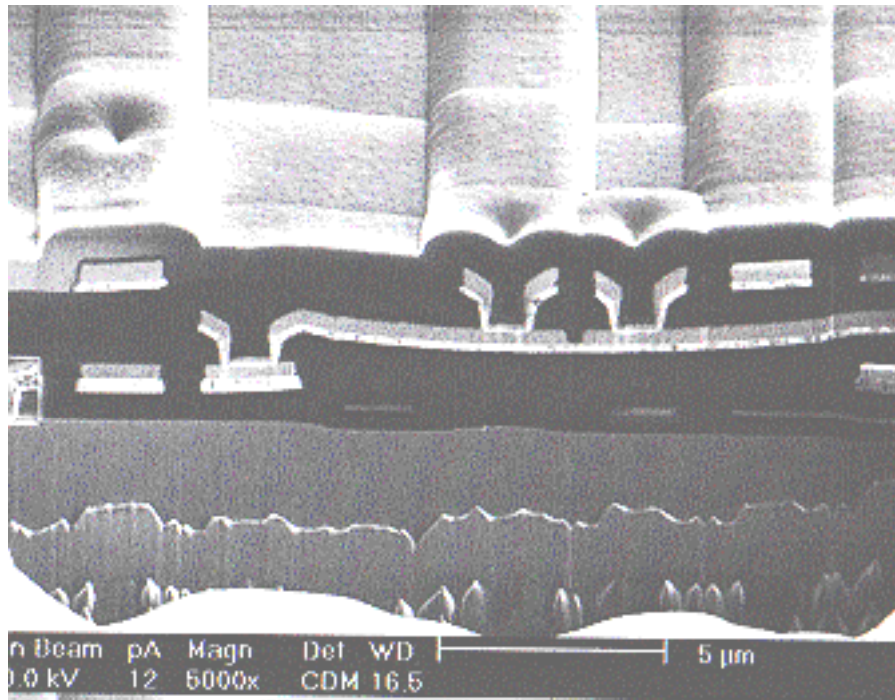


SEM WITH FOCUSED ION BEAM (FIB)

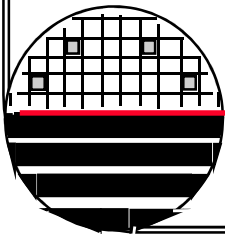


Rochester Institute of Technology
Microelectronic Engineering

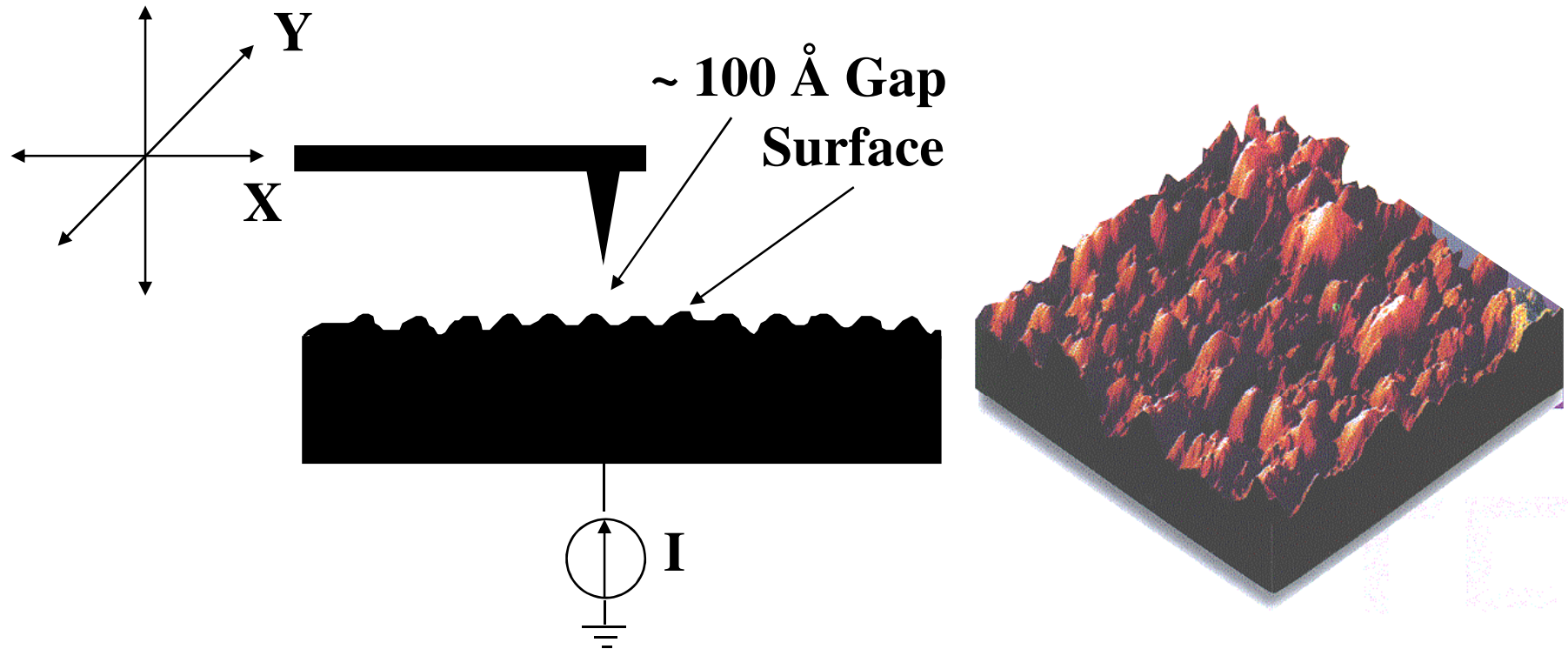
SEM WITH FOCUSED ION BEAM (FIB)



FIB allows crosssection SEM images to be made at any point by cutting a trench with a focused beam of argon ions.



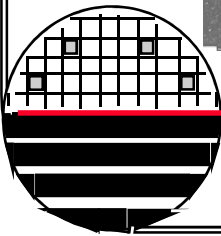
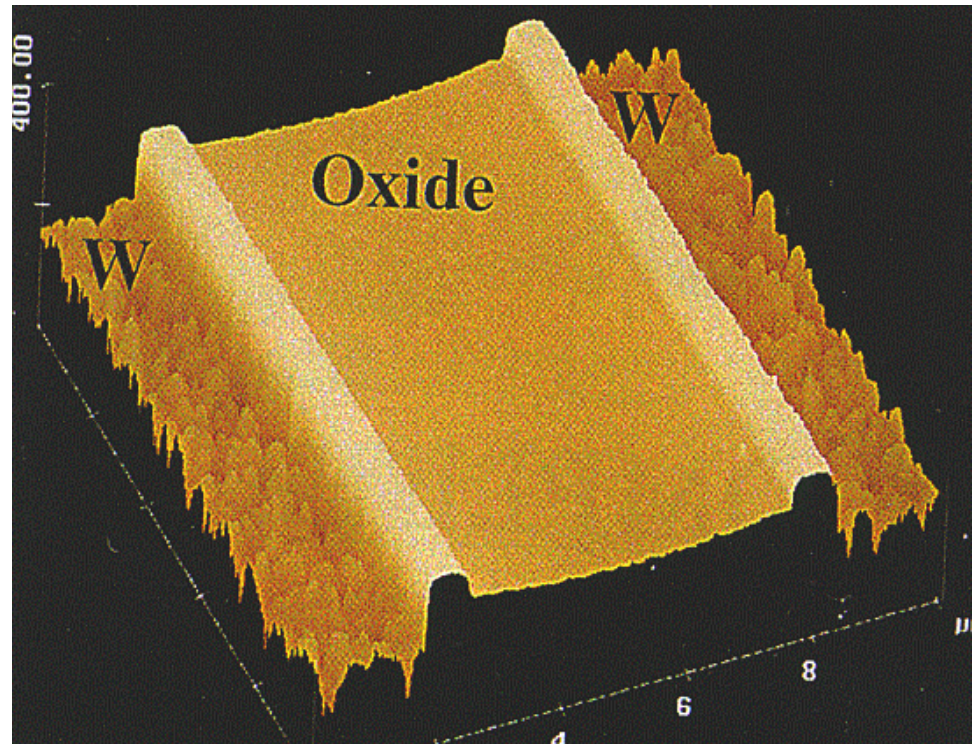
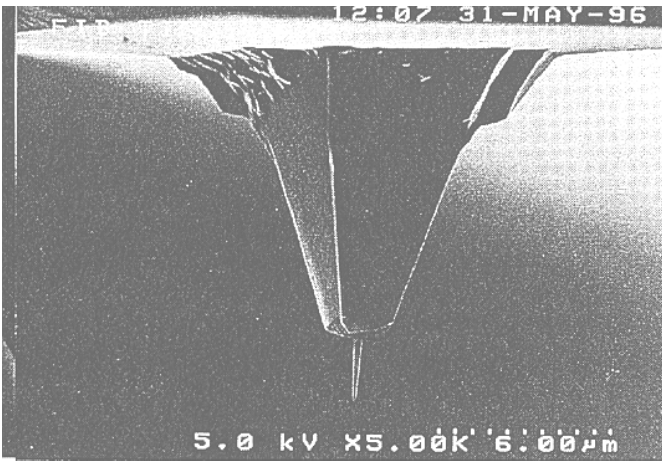
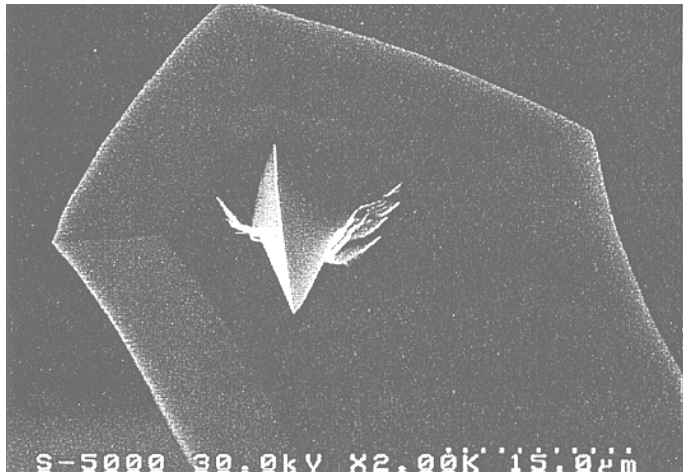
SCANNING TUNNELING MICROSCOPE (STM)



Piezoelectric Motors Scan Tip in X and Y, Electronics control Z such that the Tunneling Current I is Constant. The Control Voltage for Z is a Measure of Surface Topology

*Rochester Institute of Technology
Microelectronic Engineering*

ATOMIC FORCE MICROSCOPE (AFM)



Rochester Institute of Technology
Microelectronic Engineering

ATOMIC FORCE MICROSCOPE (AFM)

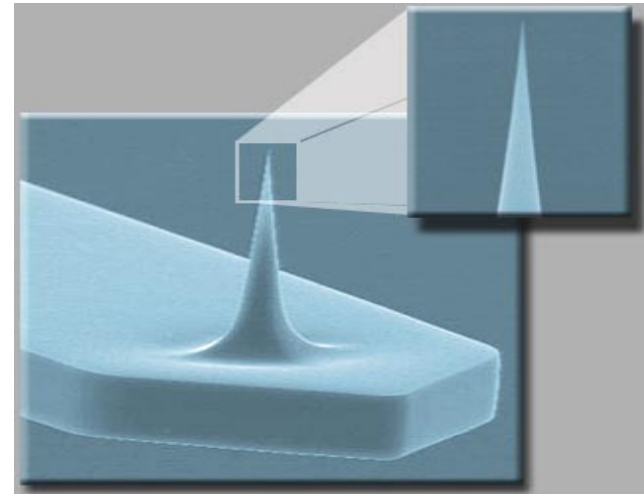
- **Standard**

Sharp Apex

Slender

Long

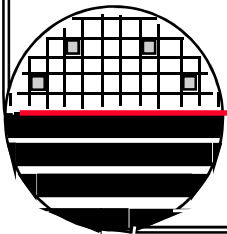
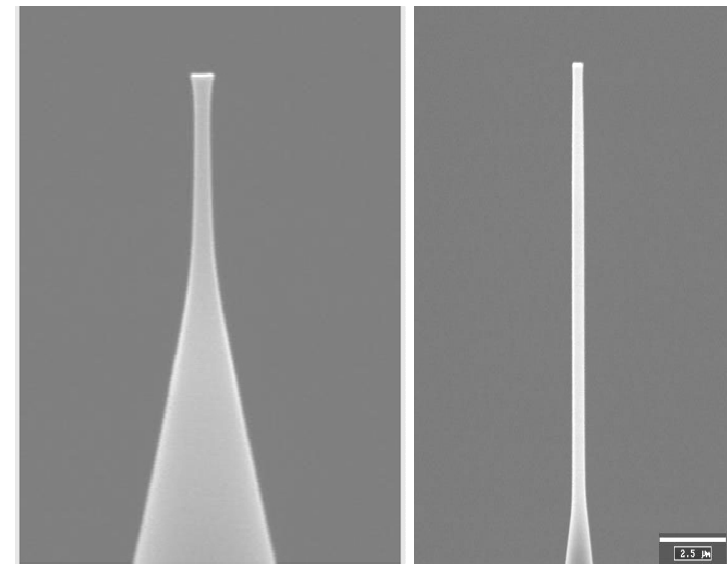
Used in Contact mode



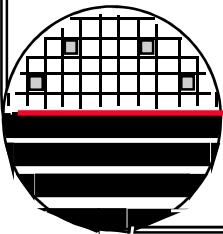
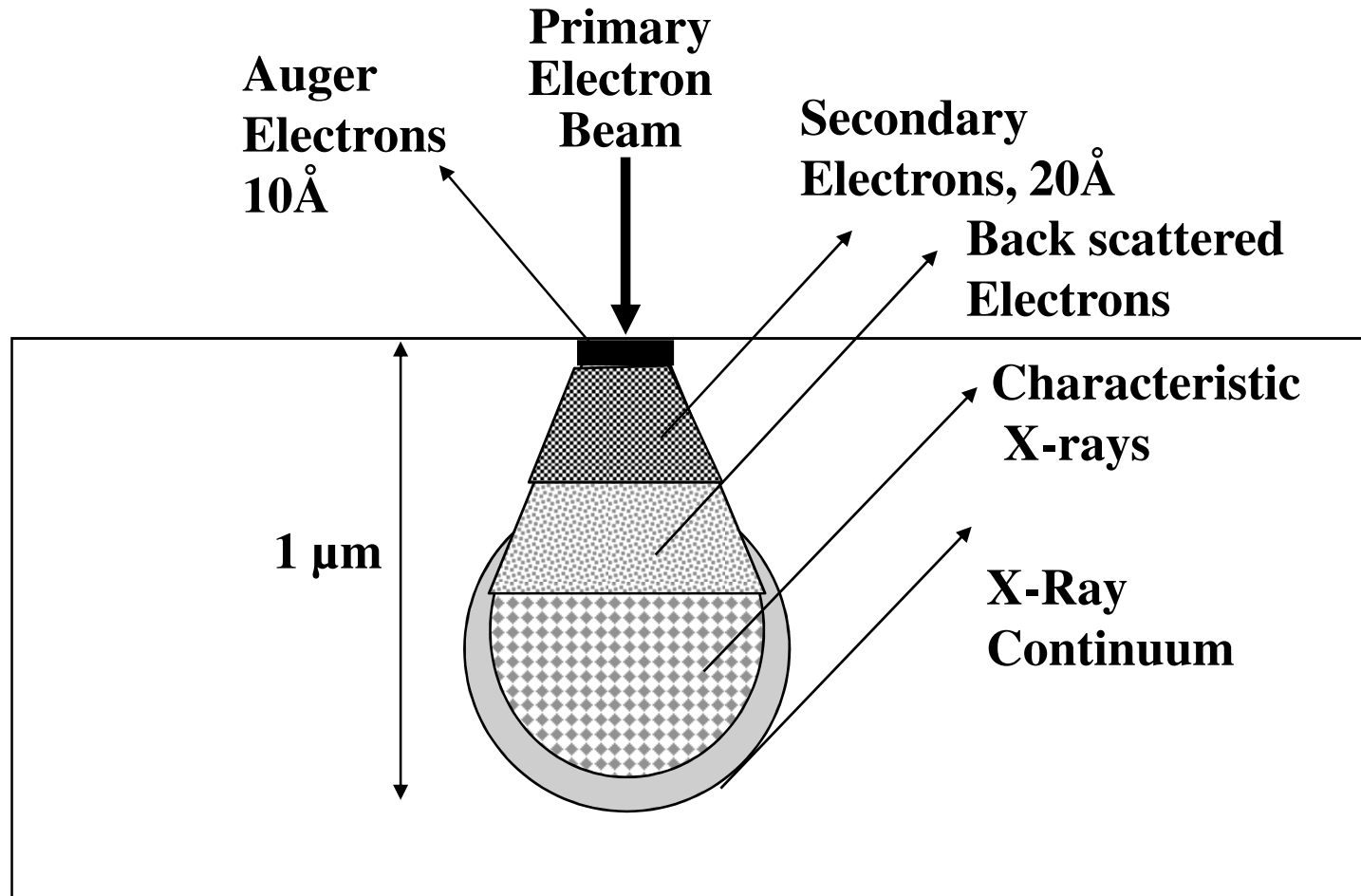
- **CD Mode (Conical and Flared)**

Flared tip able to measure undercut sidewalls

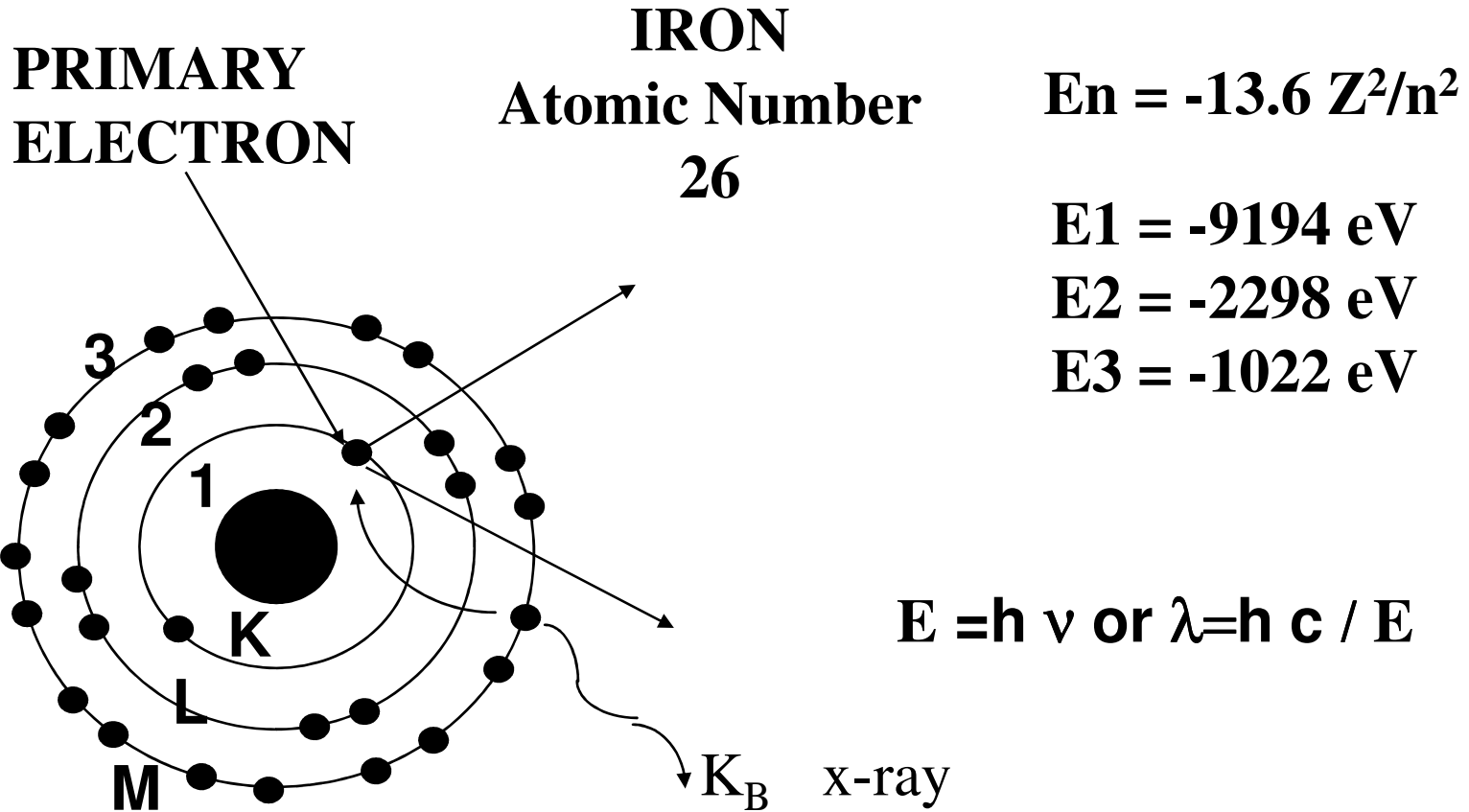
Used in non-contact mode



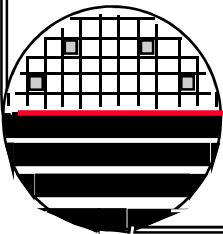
ENERGY DISPERSIVE ANALYSIS OF XRAYS (EDAX)



ENERGY DISPERSIVE ANALYSIS OF XRAYS (EDAX)

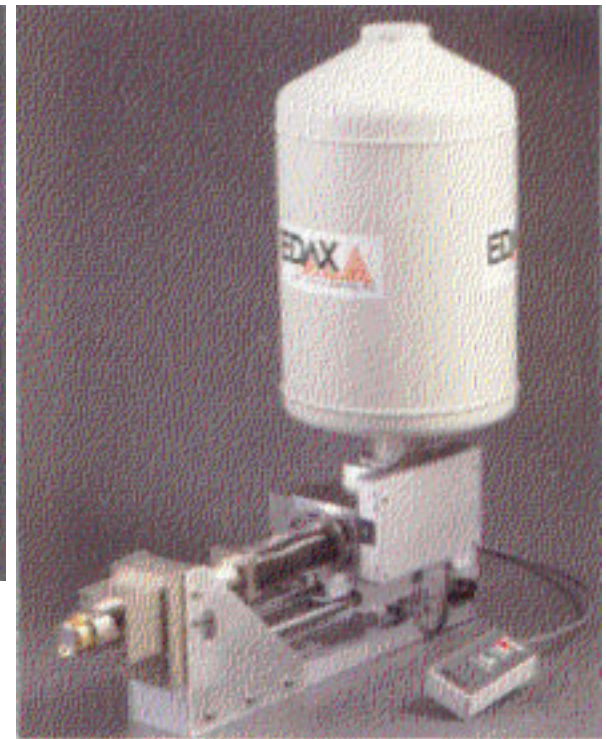
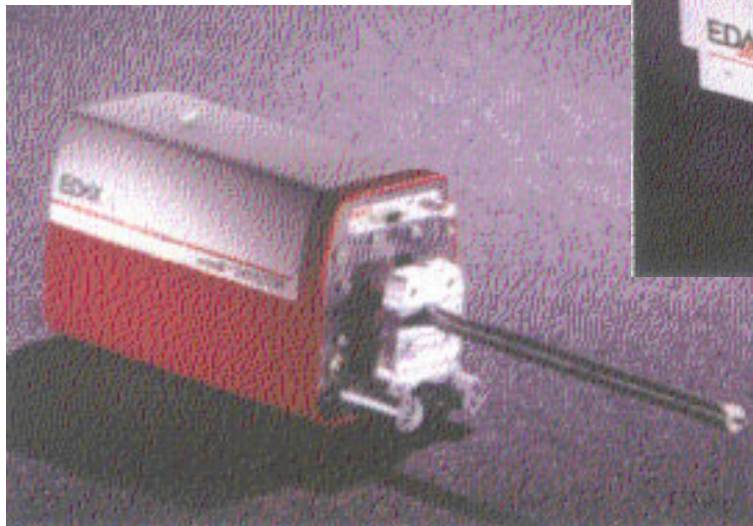


Notation: K x-rays are associated with transitions to 1st shell, L x-rays to the 2nd shell. α x-rays are between adjacent shells, B x-rays are two shells apart, etc.



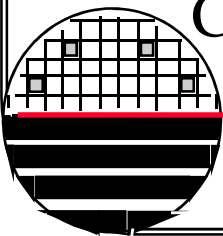
EDAX

Crystal Detector



Liquid Nitrogen Cooled
Semiconductor Detector

Cryogenic Semiconductor Detector



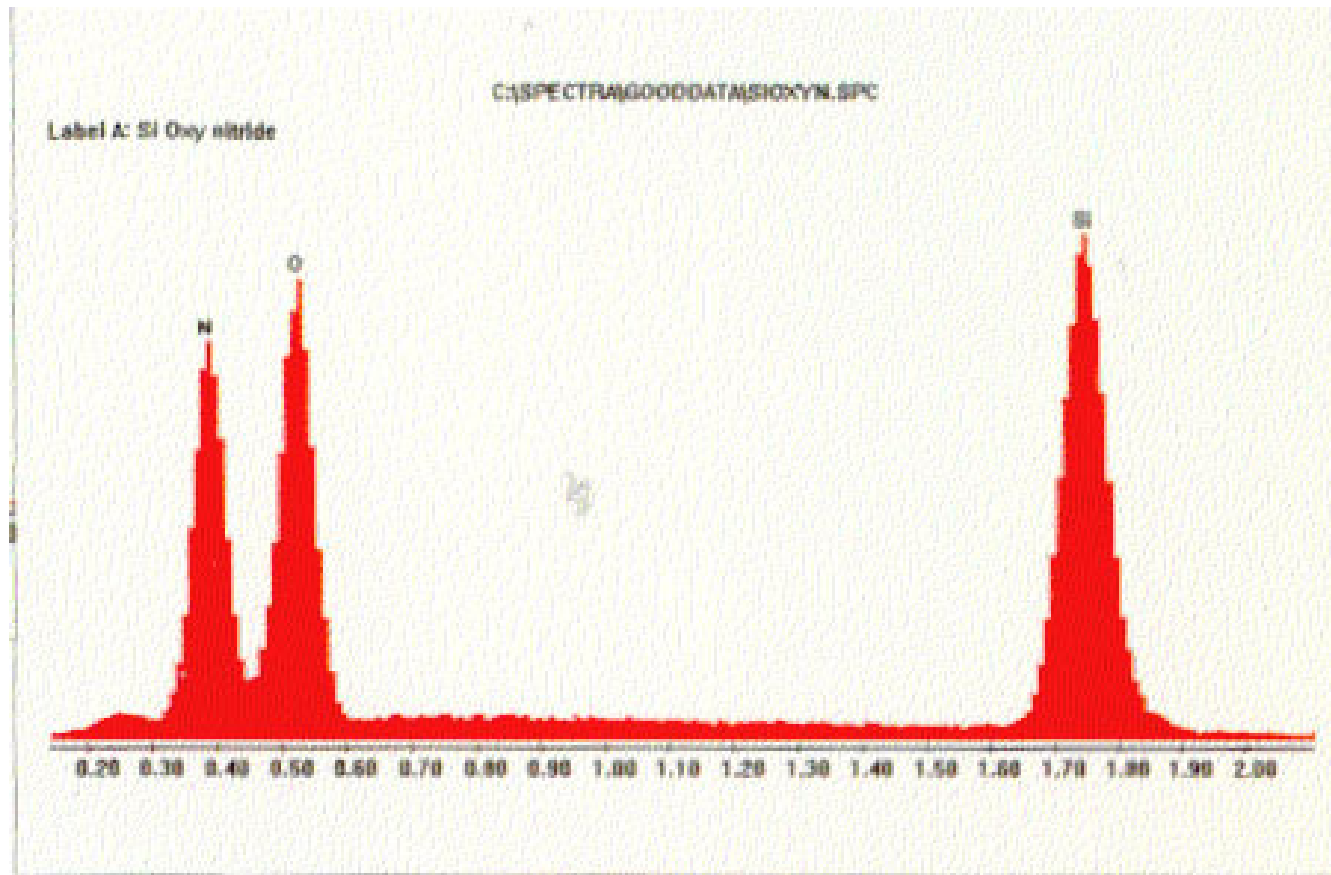
EDAX



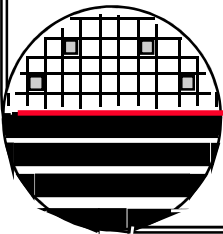
Phoenix microanalyzer including EDAM III acquisition electronics and PC.

*Rochester Institute of Technology
Microelectronic Engineering*

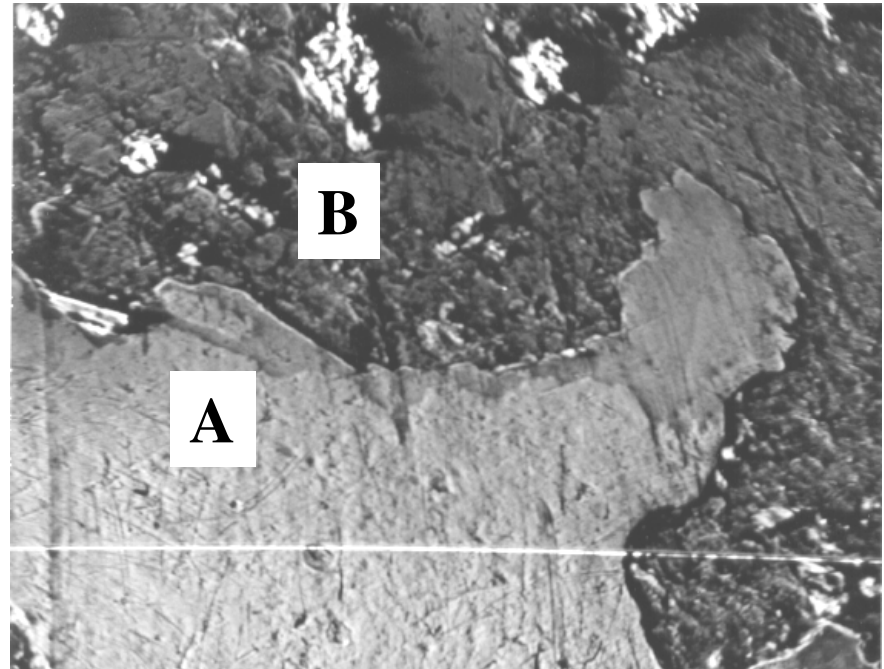
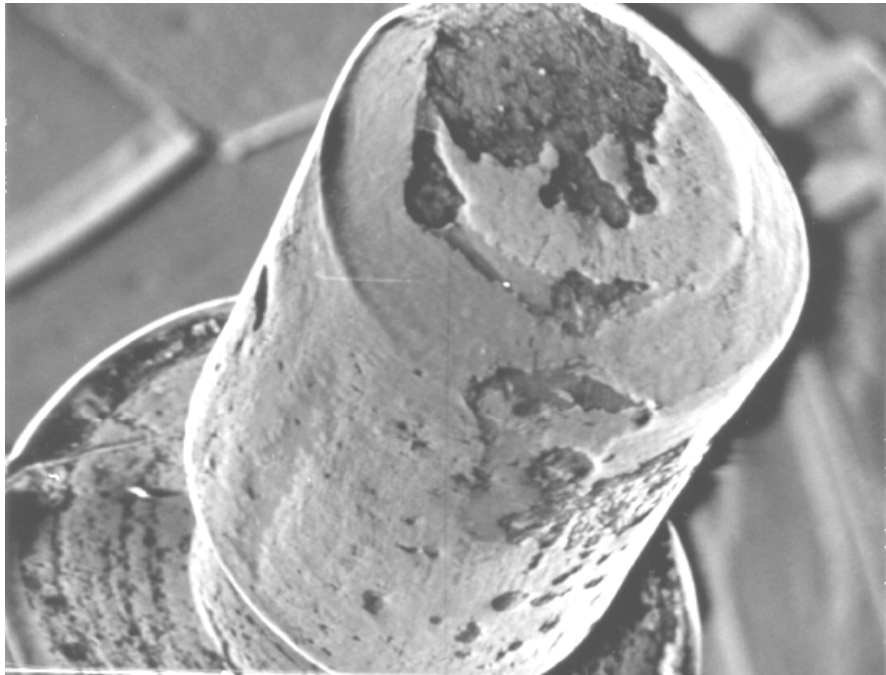
EDAX



Spectrum of silicon oxynitride acquired at 5 kV.



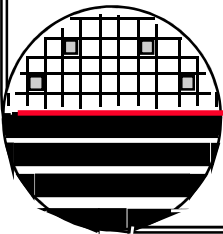
EDAX ANALYSIS OF FAILED RF PIN



Failed RF Pin: 40X

Failed RF Pin: 320X

Point A & B Analyzed using EDAX

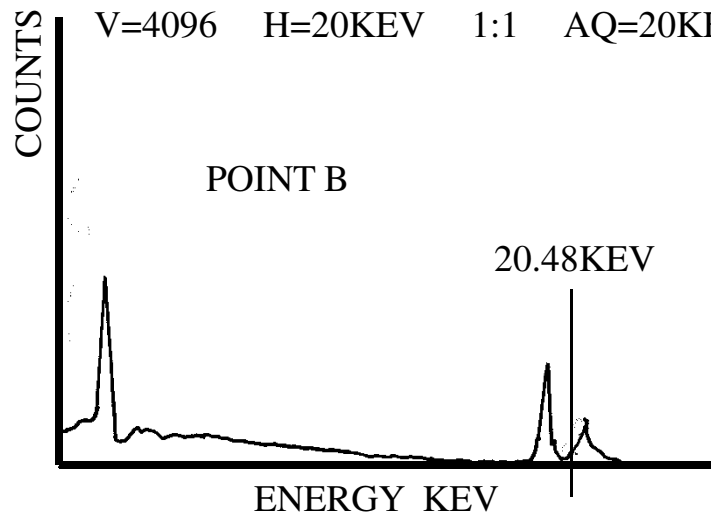


MLK MODE SELECT ELEMENT

LK Z=30 ZN

PR=S 319 SEC 0 INT

V=4096 H=20KEV 1:1 AQ=20KEV 1H

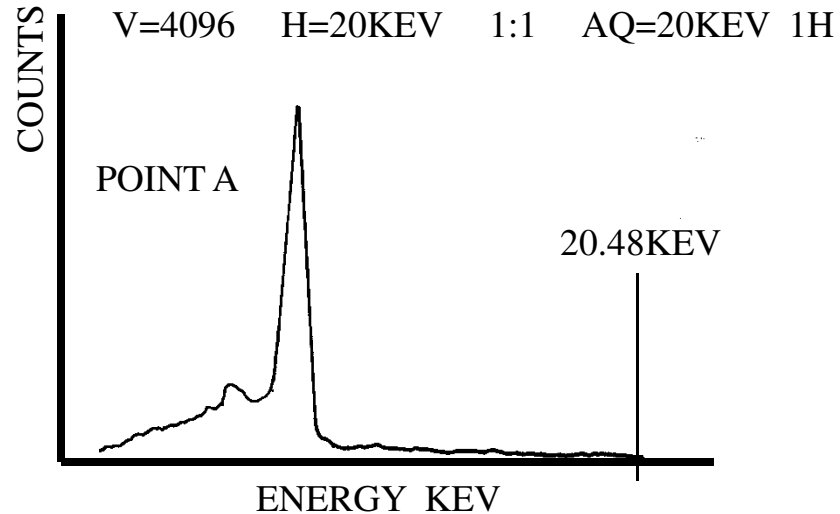


MLK MODE SELECT ELEMENT

ML Z=80 HG

PR=S 150 SEC 0 INT

V=4096 H=20KEV 1:1 AQ=20KEV 1H

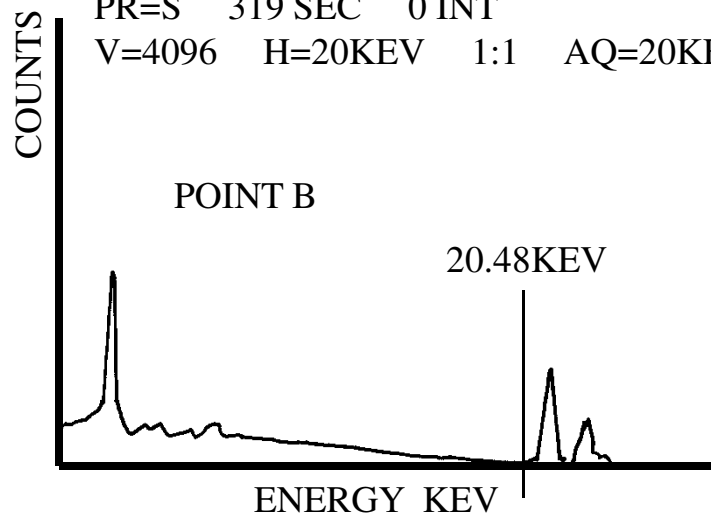


MLK MODE SELECT ELEMENT

LK Z=29 CU

PR=S 319 SEC 0 INT

V=4096 H=20KEV 1:1 AQ=20KEV 1H

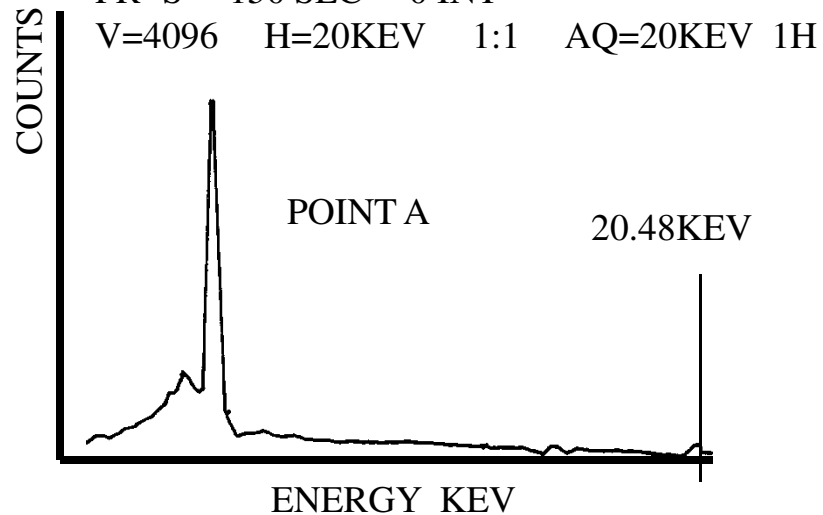


MLK MODE SELECT ELEMENT

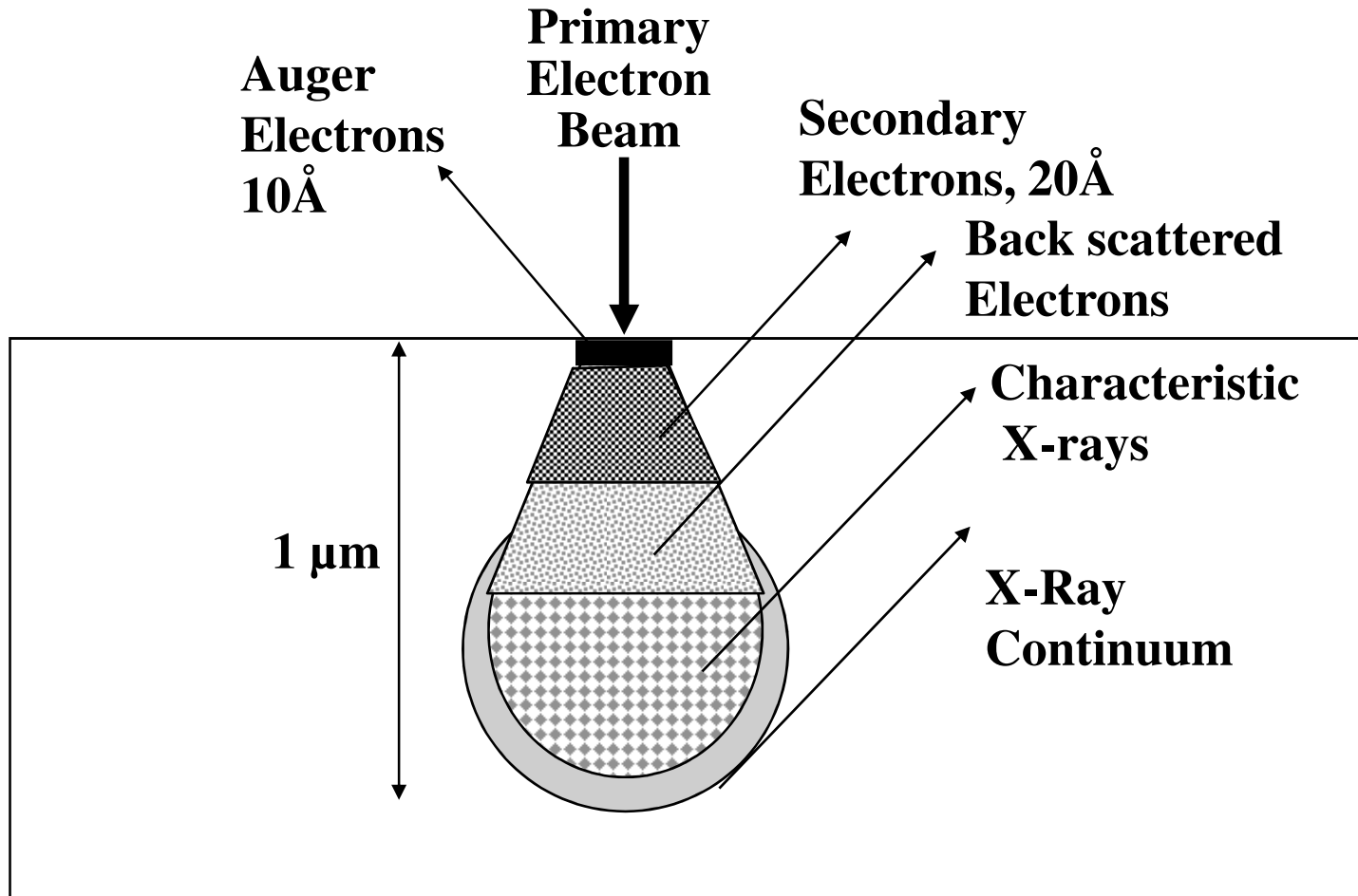
MLK Z=41 NB

PR=S 150 SEC 0 INT

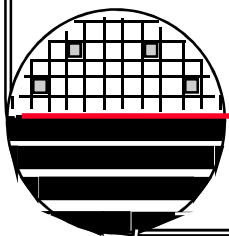
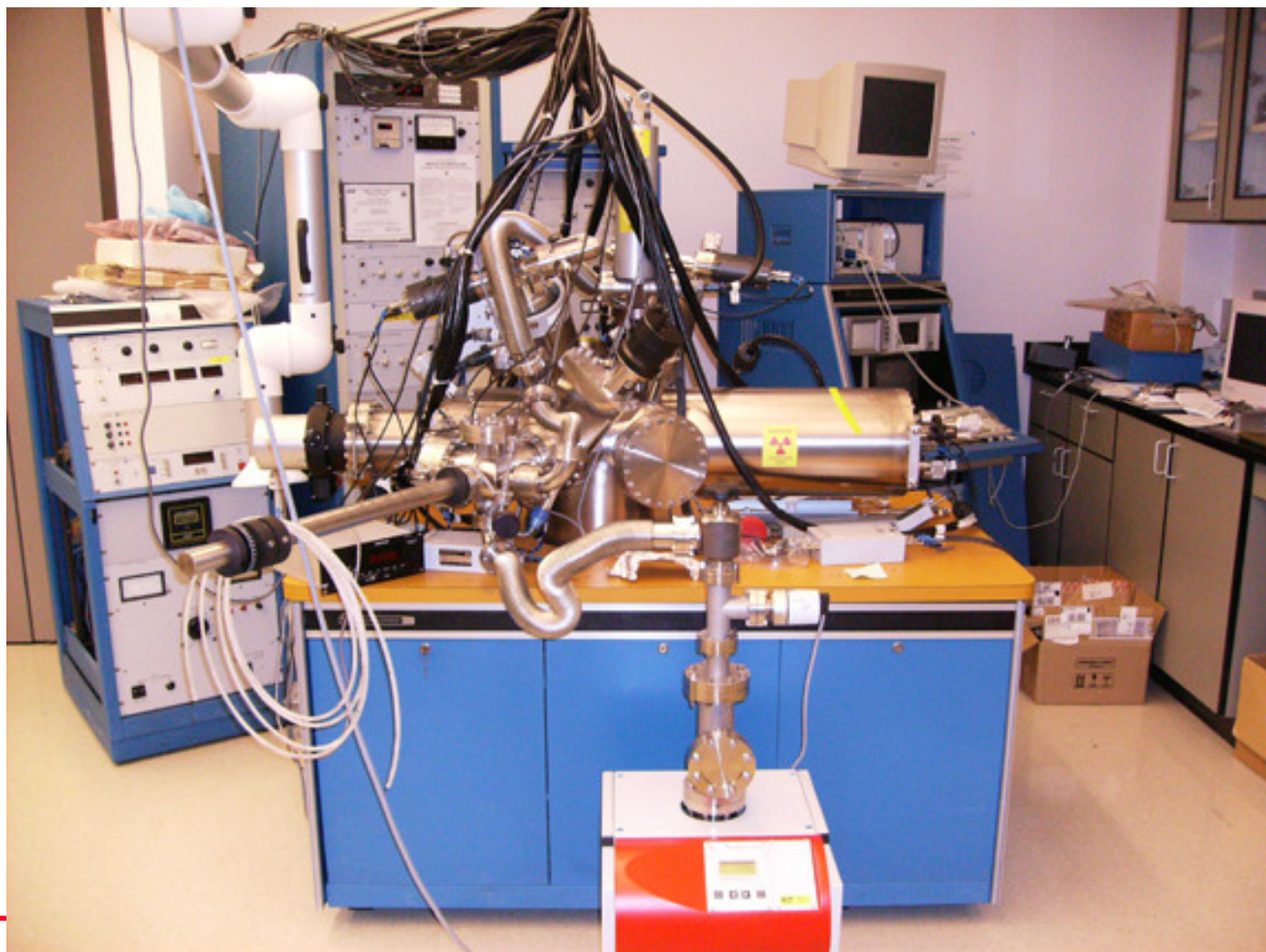
V=4096 H=20KEV 1:1 AQ=20KEV 1H



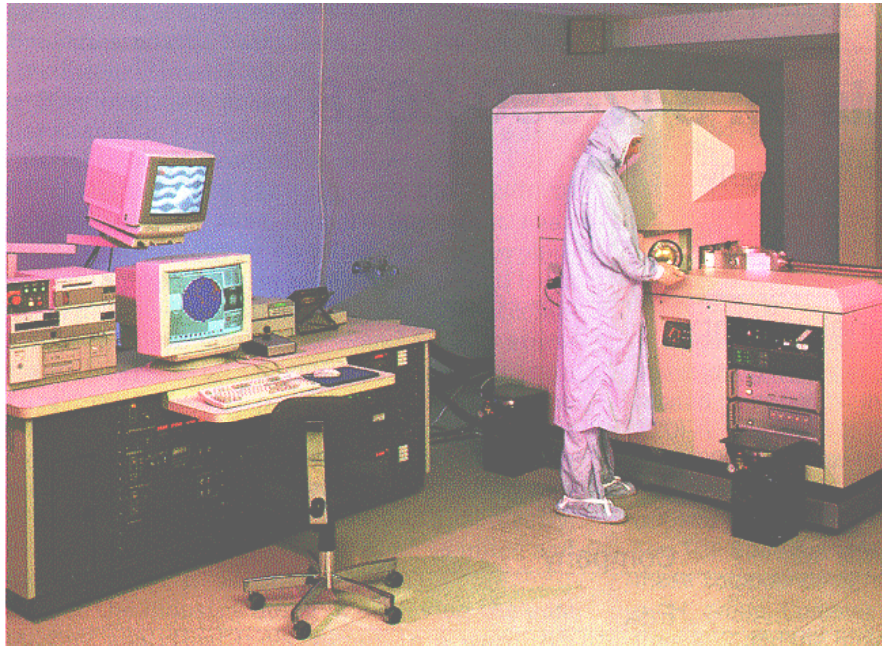
AUGER ELECTRON SPECTROSCOPY



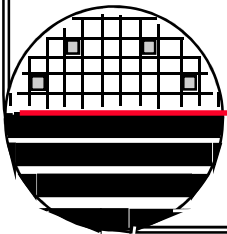
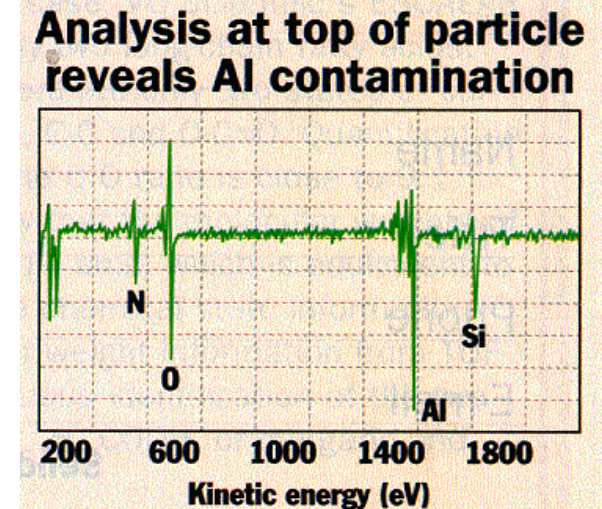
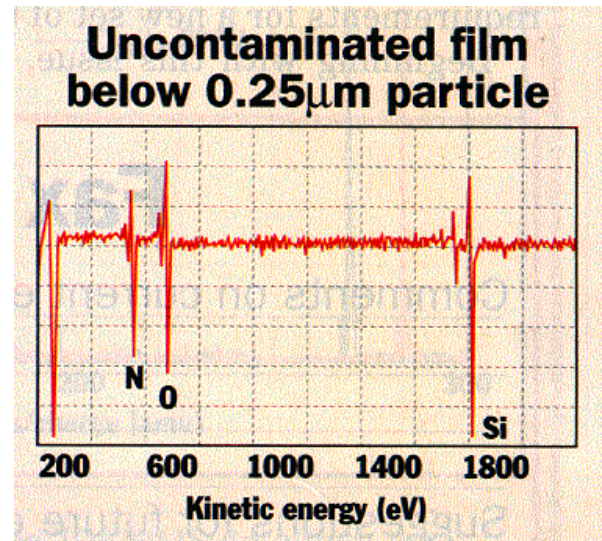
AUGER



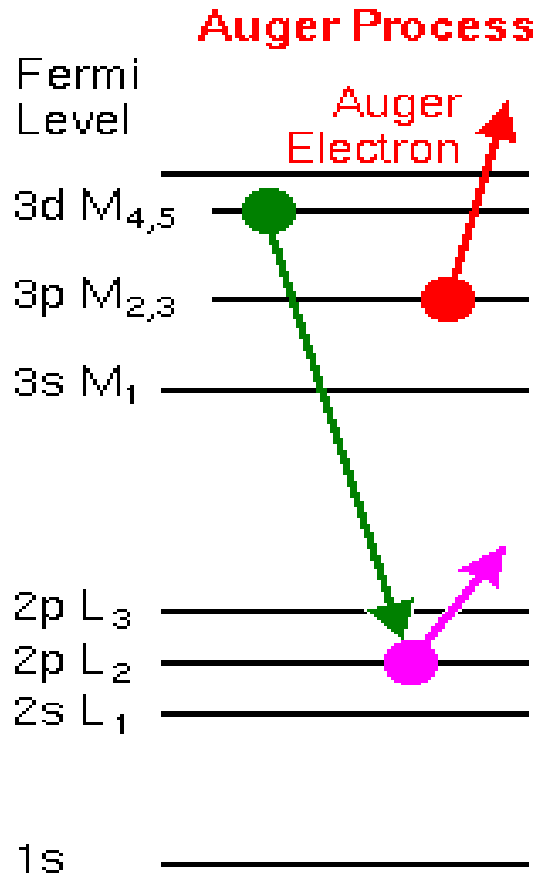
AUGER



Auger analysis showed an aluminum particle contaminated the wafer.



AUGER

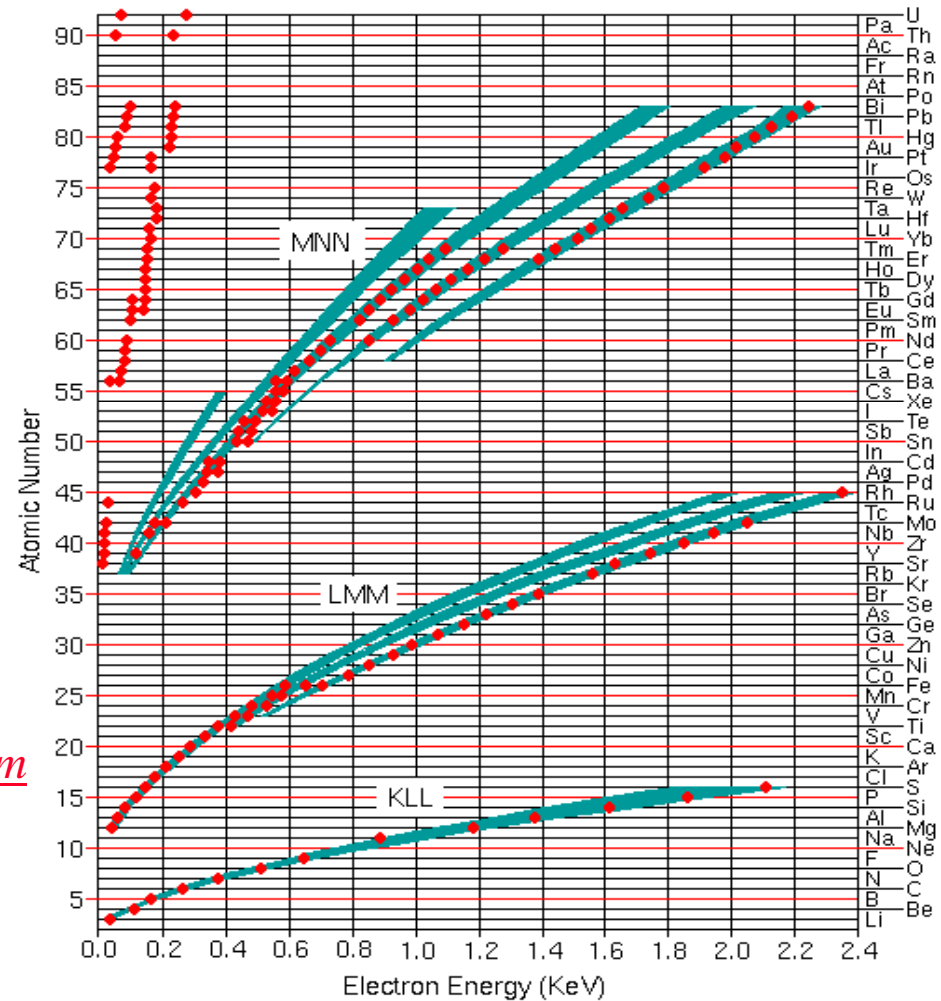


- **Simultaneous Process**
- **Ionization of Core Electron**
- **Upper level electron falls into lower energy state**
- **Energy release from second electron allows Auger electron to escape**
- **The illustrated LMM Auger electron energy is ~423 eV**
($E_{Auger} = E_{L2} - E_{M4} - E_{M3}$)

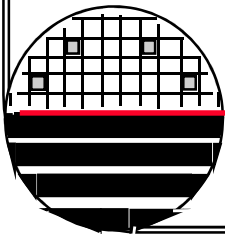
<http://www.cea.com/cai/augtheo/process.htm>

AUGER

- Chart of principal Auger electron energies
- Dots indicate electron energies for principal Auger peaks for each element



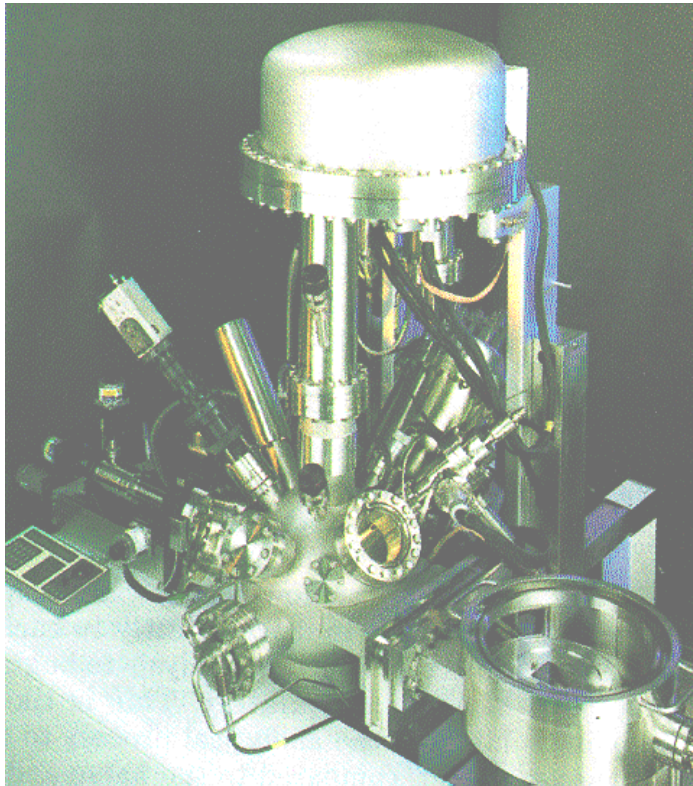
<http://www.cea.com/cai/augtheo/energies.htm>



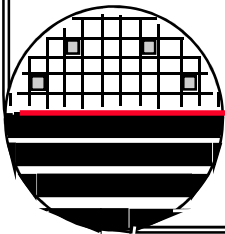
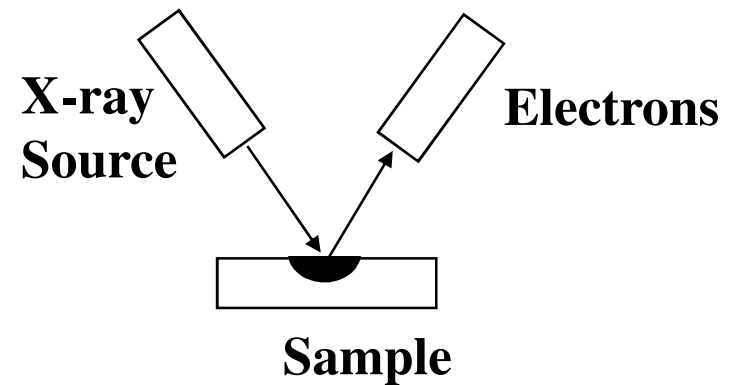
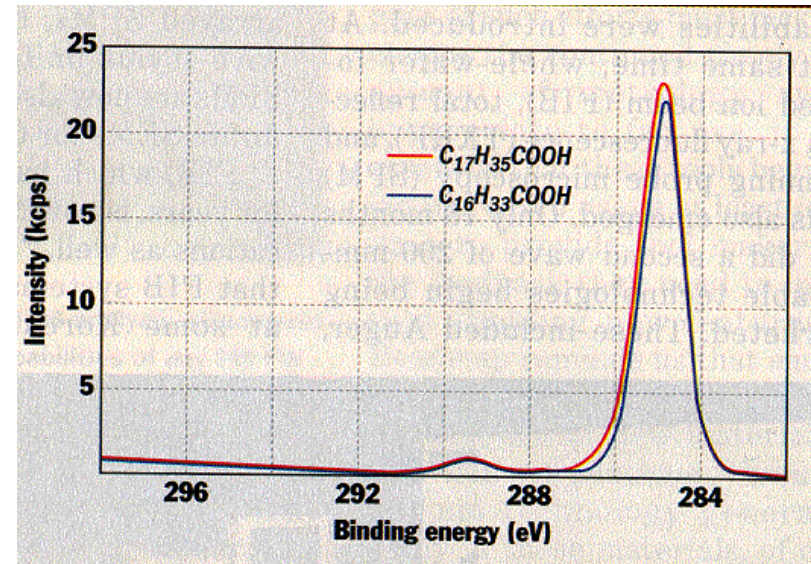
Rochester Institute of Technology
Microelectronic Engineering

ESCA or XPS

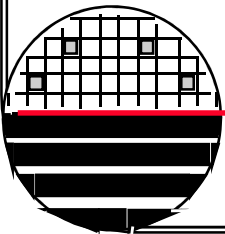
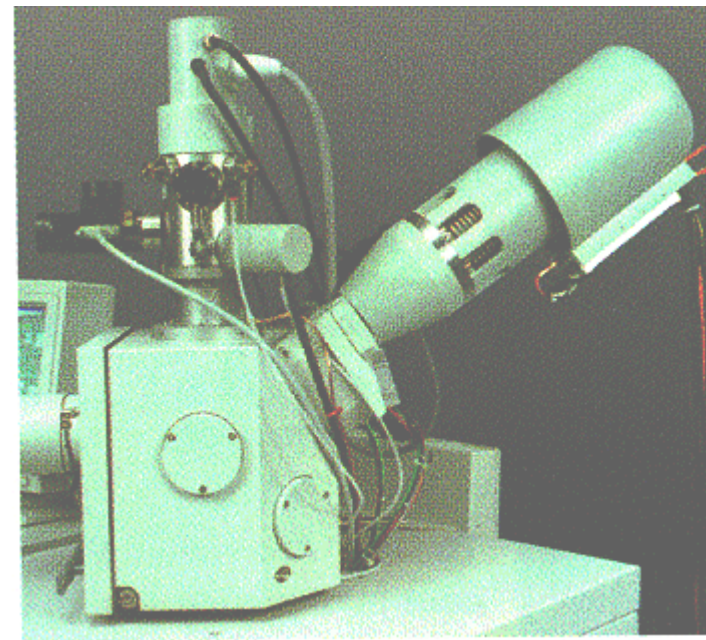
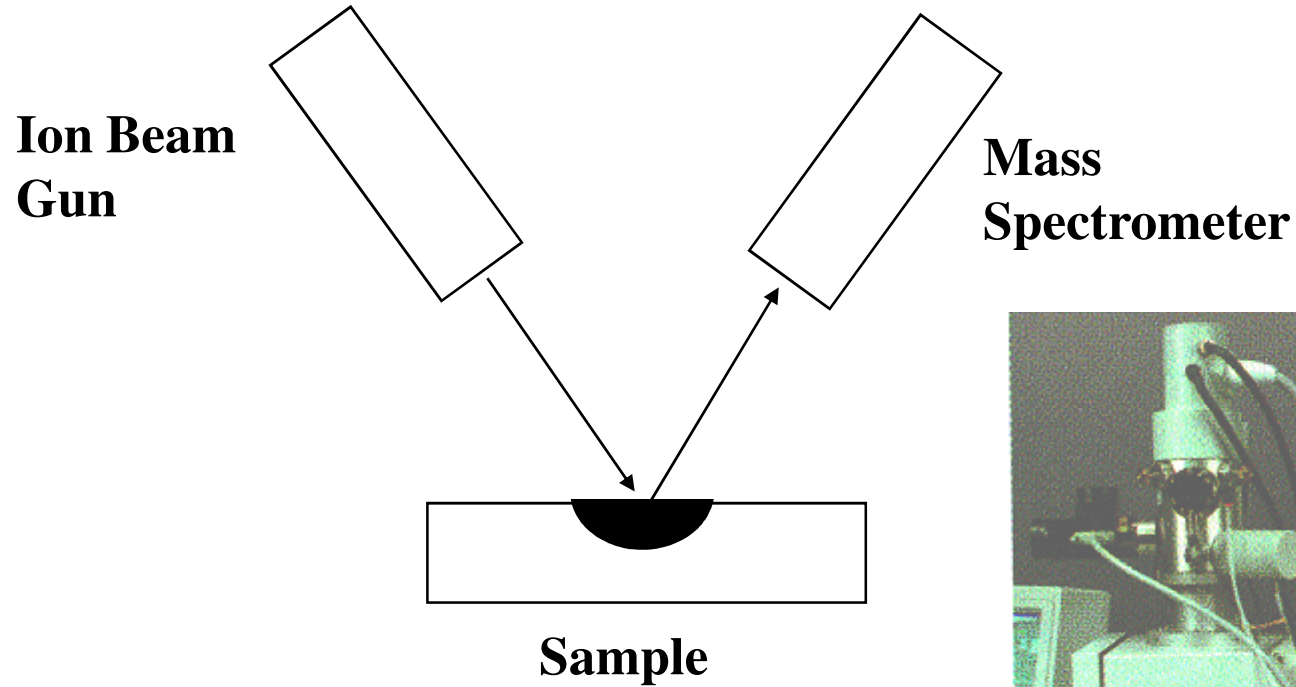
Electron Spectroscopy for Chemical Analysis (ESCA) or X-ray Photo Electron Spectroscopy (XPS)



Rochester Institute of Technology
Microelectronic Engineering

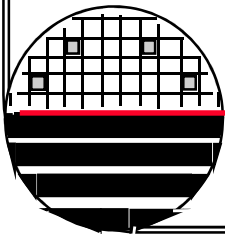
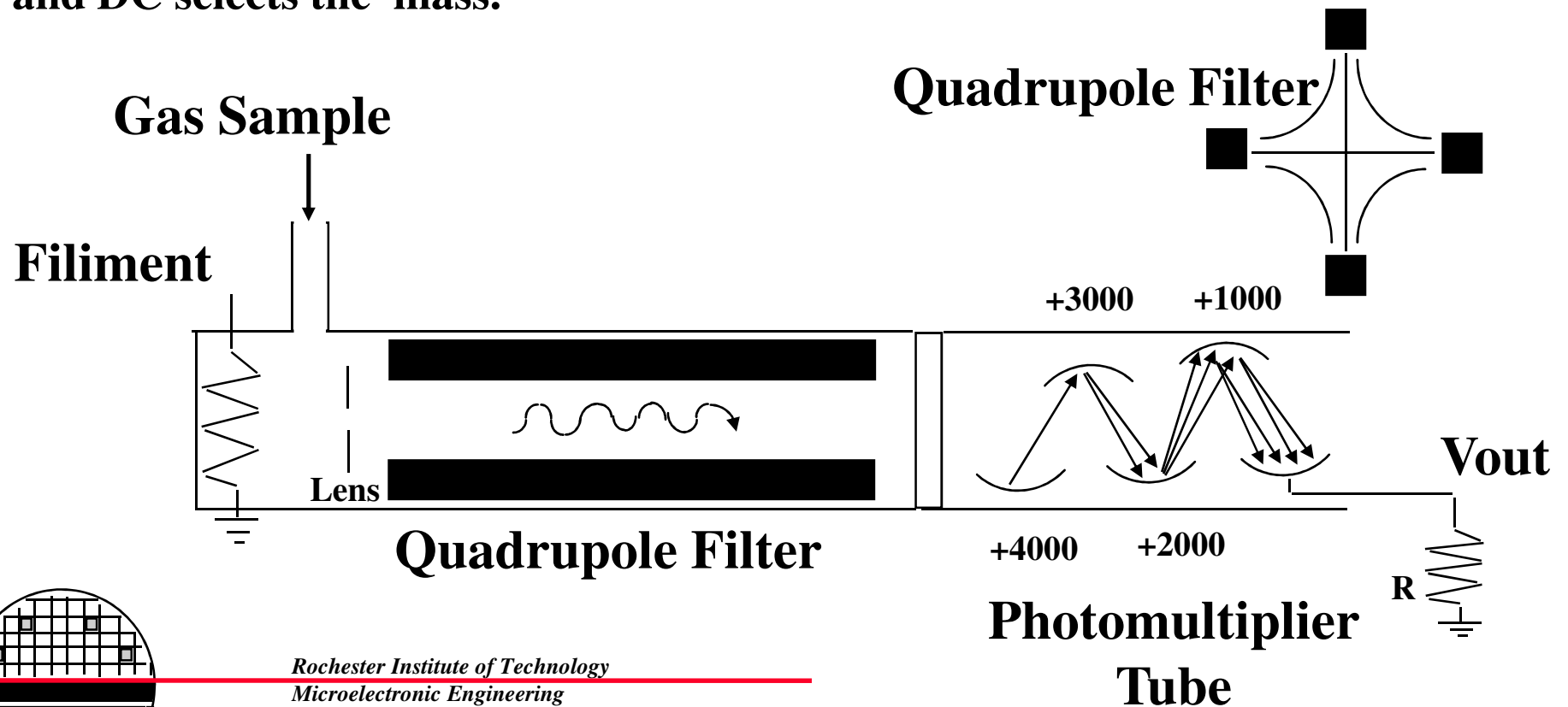


SECONDARY ION MASS SPECTROSCOPY (SIMS)



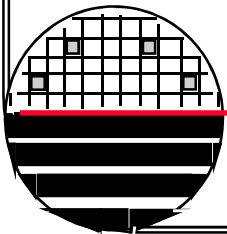
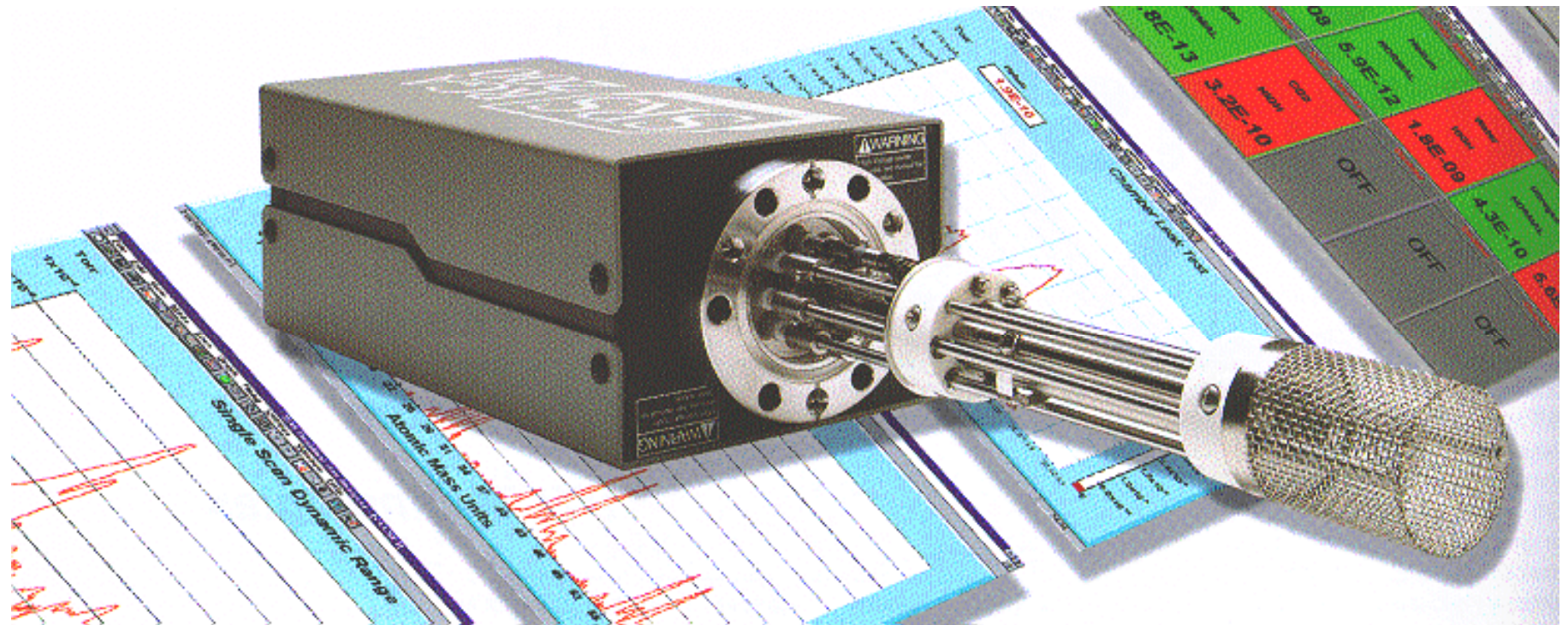
RESIDUAL GAS ANALYZER (RGA)

The Quadrupole Filter has voltages such that down the center there is a zero potential equipotential surface. Only ions of a certain mass make it all the way to the photomultiplier tube. The voltage applied to the filter at radio frequency and DC selects the mass.



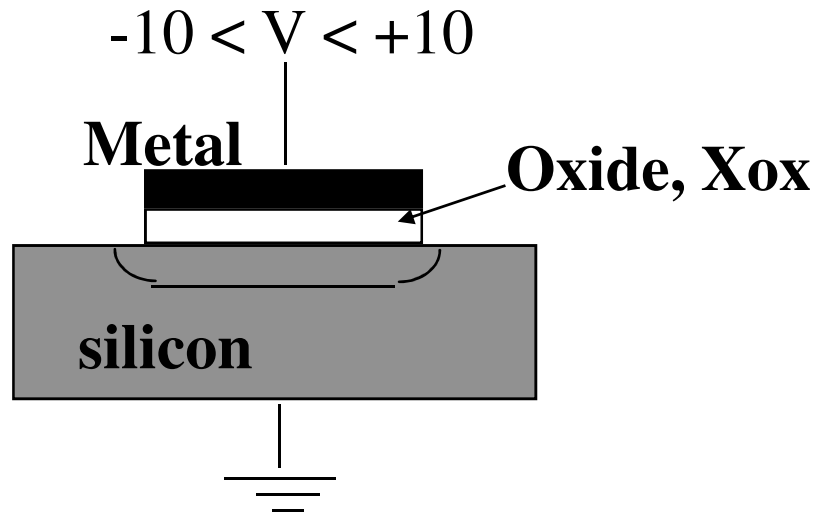
Surface Analysis

RGA



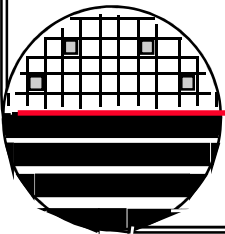
Rochester Institute of Technology
Microelectronic Engineering

CAPACITANCE VOLTAGE MEASUREMENTS

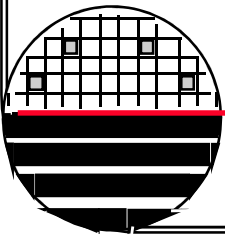
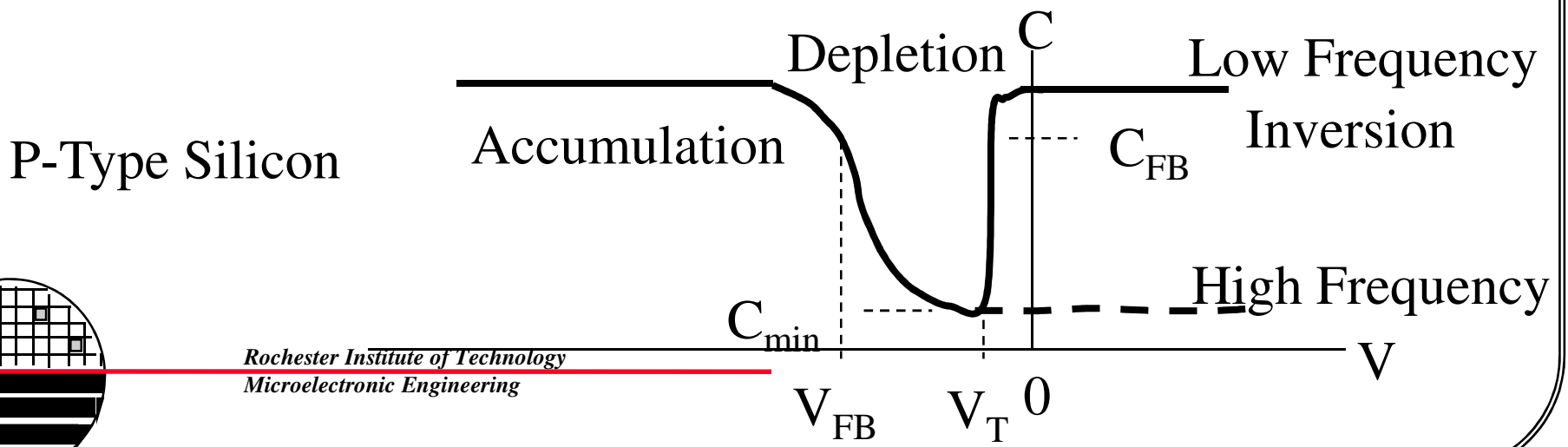
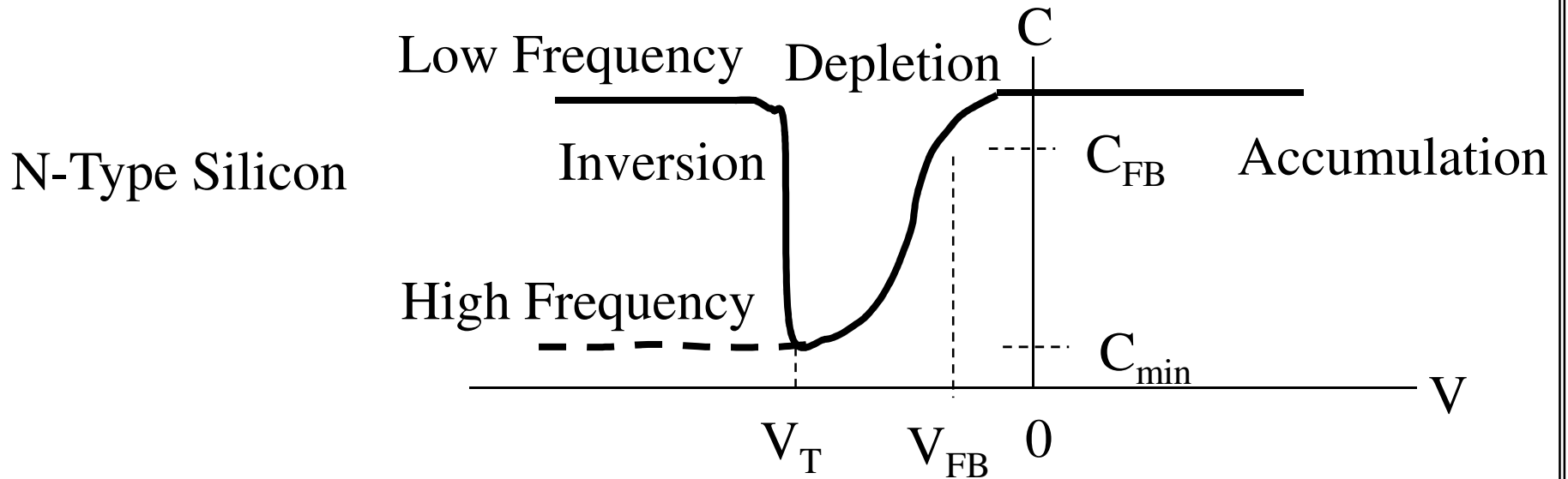


$$C_{ox} = \epsilon_0 \epsilon_r \text{Area} / X_{ox}$$

Apply a DC voltage (V) to the capacitor and measure the capacitance. High frequency and low frequency capacitance measurement techniques are available.



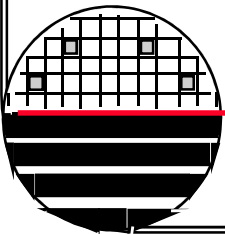
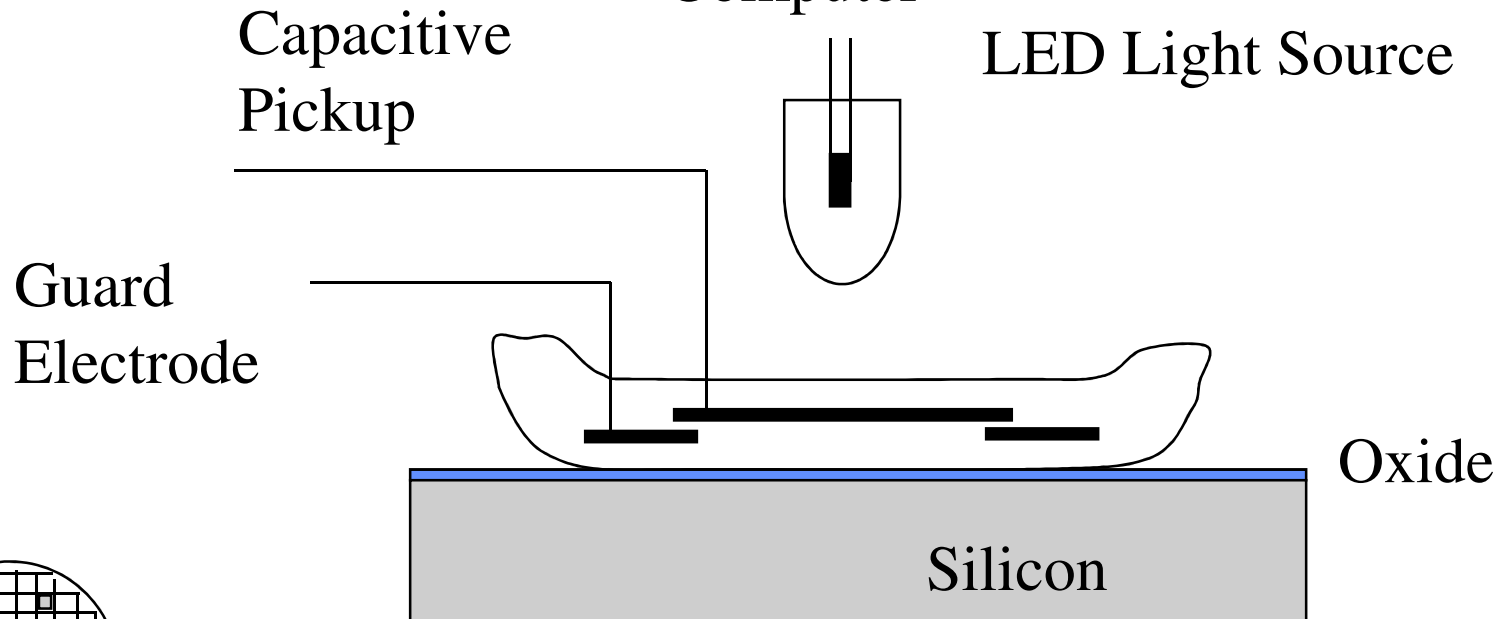
CV MEASUREMENTS



Surface Analysis

SCA

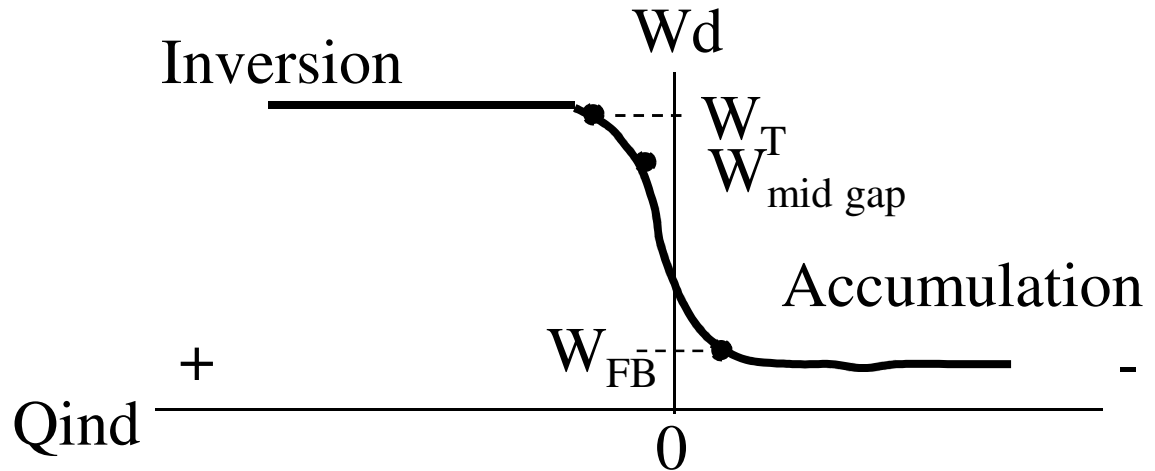
Signal Amplifier
High Voltage Amplifier
Light Controller and Modulator
Data Acquisition
Computer



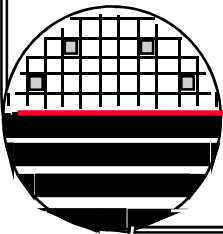
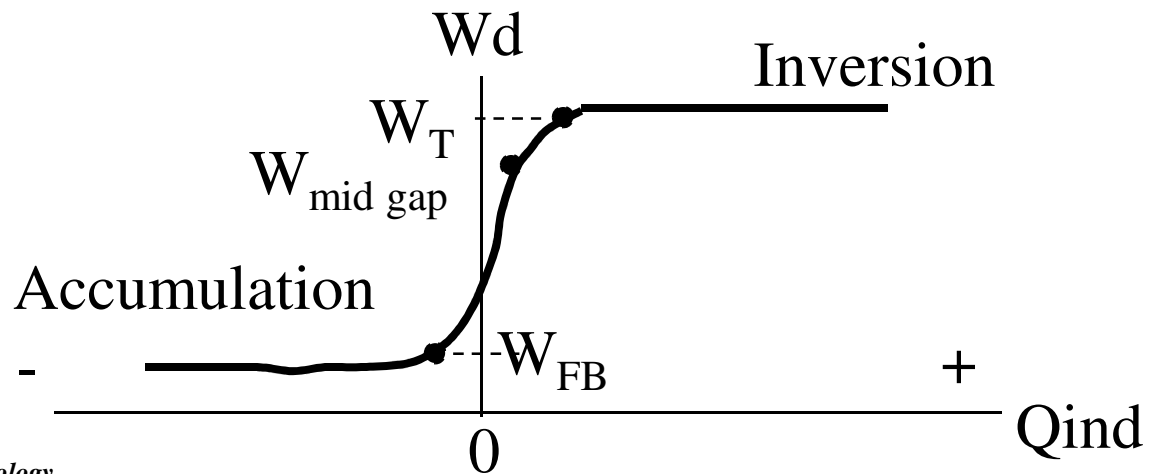
Rochester Institute of Technology
Microelectronic Engineering

SCA

P-type Wafer



N-type Wafer



SCA-2500 SETUP

Login: FACTORY

Password: OPER

<F1> Operate

<F1> Test **Place the blank spot in middle of wafer on center of the stage**

Select (use arrow keys, space bar, page up, etc)

PROGRAM = FAC-P or FAC-N

LOT ID = F990909

WAFER NO. = D1

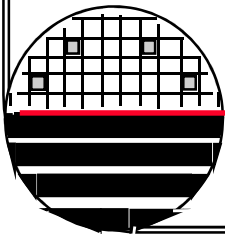
TOX = 463 (from nanospec)

<F12> start test and wait for measurement

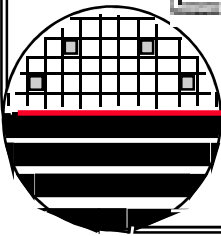
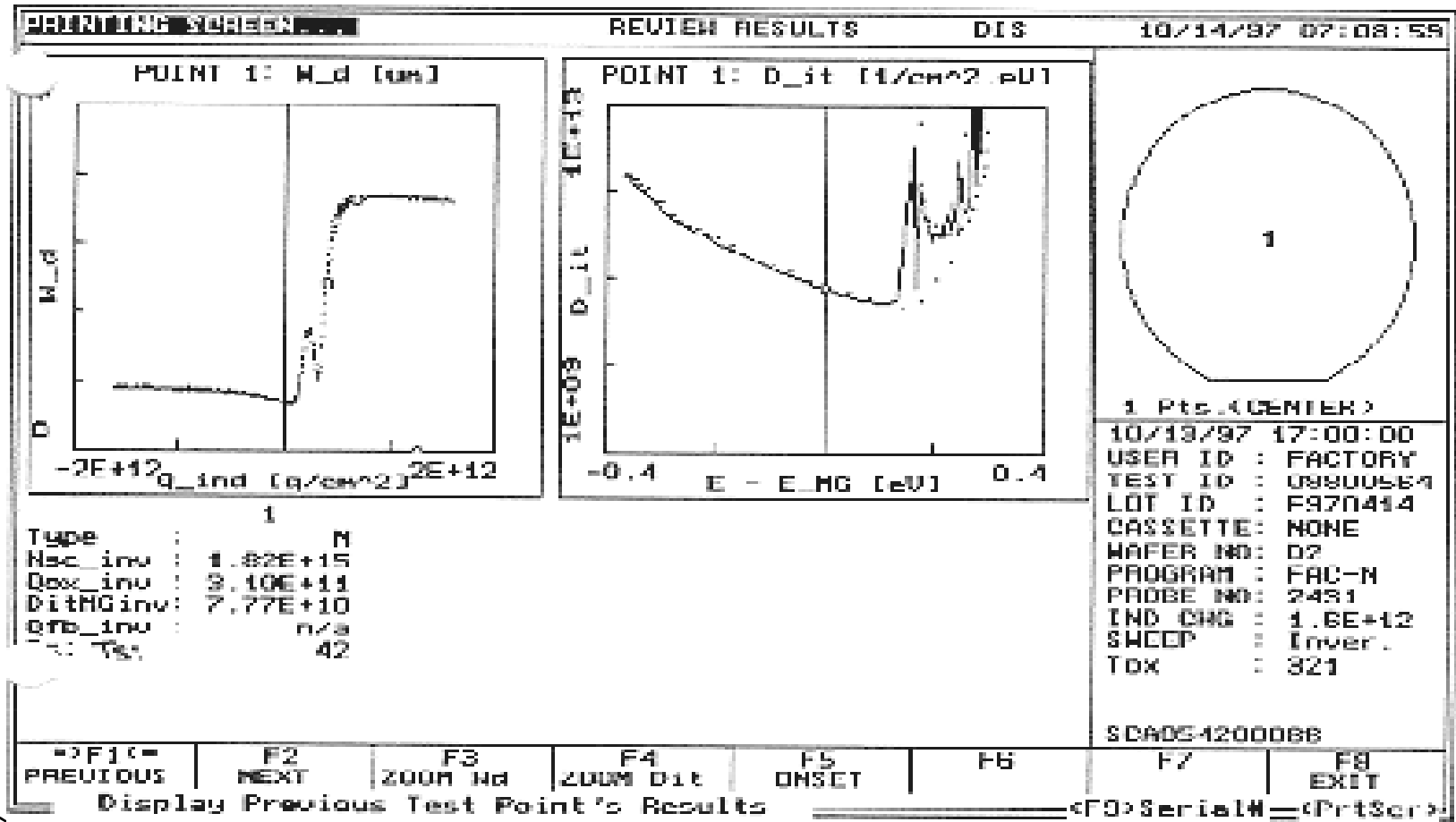
<Print Screen> print results

<F8> exit and log off

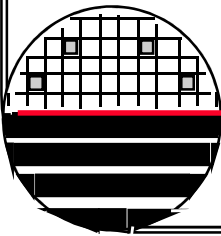
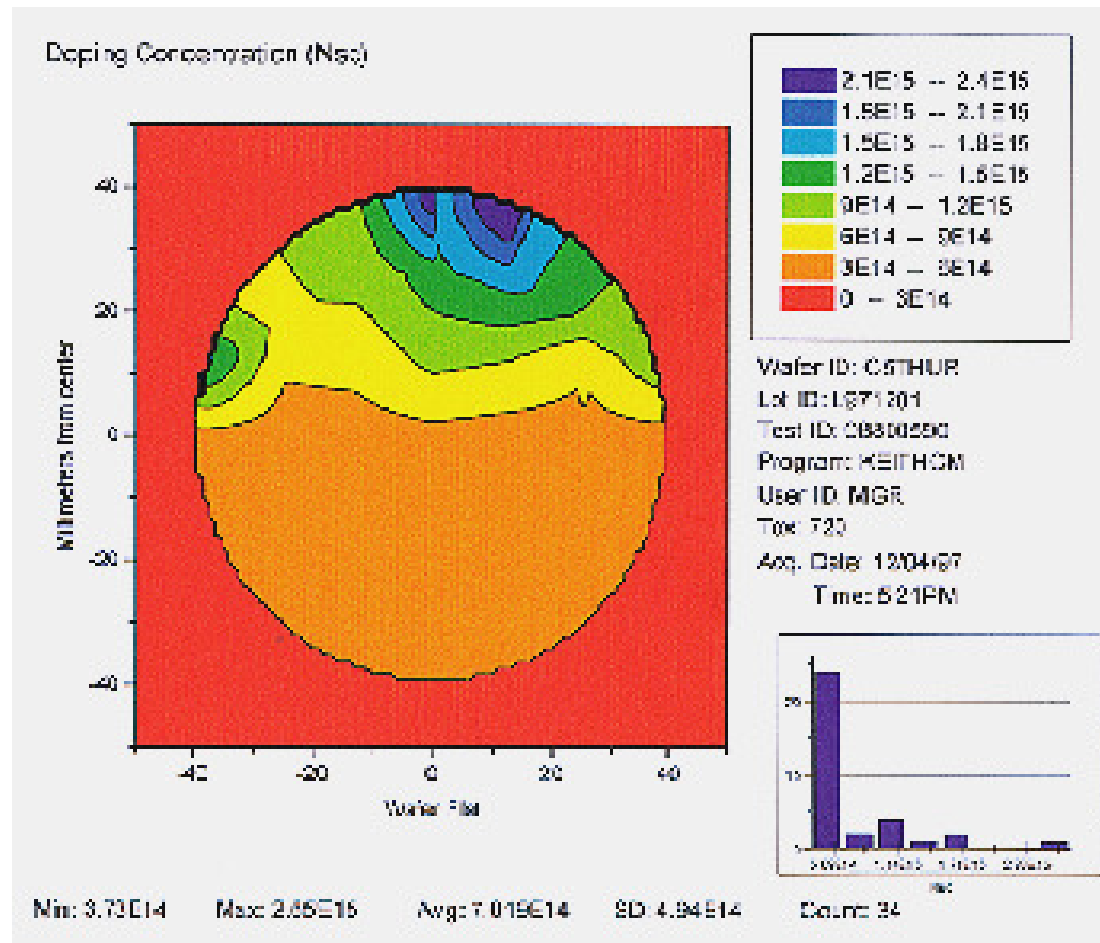
**<ESC> can be used anytime, but wait for
current test to be completed**



EXAMPLE OF SCA OUTPUT MEASURED AT RIT

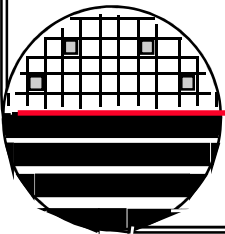


EXAMPLE OF SCA OUTPUT MEASURED AT RIT



REFERENCES

1. Scanning Electron Microscopy, Michael T. Postek, et, al., Ladd Research Industries, Inc., 1980.
2. Micro-X7000 Operating Manual, Kevex Corporation, 1101 Chess Drive, Foster City, CA 94404, 1982.
3. EDAX Inc., 91 McKee Drive, Mahwah, NJ 07430-9978, Tel (201) 529-3156
4. AFM see, <http://spm.phy.bris.ac.uk/techniques/AFM/>, and <http://www.fys.kuleuven.ac.be/vsm/spm/images/introduction/afm.html>



HOMEWORK: SURFACE

1. Calculate the wavelength of the K_{α} and L_B x-ray for copper.]
2. Explain how SIMS gives doping profiles.
3. Why can't Auger and a ESCA give doping profiles.

